INTEGRATED CIRCUITS, SILICON MONOLITHIC,

CMOS ANALOGUE MULTIPLEXER/DEMULTIPLEXER,

BASED ON TYPE 4067B

ESCC Detail Specification No. 9408/009

ISSUE 1

October 2002

Document Custodian: European Space Agency - see https://escies.org

LEGAL DISCLAIMER AND COPYRIGHT

european space agency
agence spatiale européenne

Pages 1 to 61

INTEGRATED CIRCUITS, SILICON MONOLITHIC,

CMOS ANALOGUE MULTIPLEXER/DEMULTIPLEXER,

BASED ON TYPE 4067B

ESA/SCC Detail Specification No. 9408/009

space components
coordination group

Issue/Rev.	Date	Approved by	
		SCCG Chairman	ESA Director General or his Deputy
Issue 2	March 1991		
Revision 'A'	March 1992		
Revision 'B'	October 1994		
Revision 'C'	April 2001		

DOCUMENTATION CHANGE NOTICE

Rev. Letter	Rev. Date	CHANGE Reference		Item	Approved DCR No.
		This Issue supersedes Issue 1 and incorporates all modifications defined in Revisions 'A' and 'B' to Issue 1 and the following DCR's:-			
		Cover Page			None
		DCN			None
		Para. 1.1	:	"having fully buffered outputs" added to 1st sentence	23442
		Para. 1.10	:	Last sentence rewritten to include ESD Class and Minimum Critical Path Failure Voltage	23385
		Table 1(a)	:	Table amended	22398
		Table 1(b)	:	No. 9, package soldering temperatures changed	22314
			:	Notes - New Note 7 added	22314
				- Previous Note 7 renumbered "8" and corrected	23442
		Figure 2(a)	:	Table corrected	23247/ 23270
		Figure 2(b)	:	"CKT A" deleted from Title	22398
		Figure 2(c)	:	Deleted in toto	22398
		Figure 2(d)	:	Title amended to "2(c)"	22398
			:	Table corrected	23247
		Notes to Figures	:	In Title and Note 1, 2(d) amended to "2(c)"	22398
		Figure 3(a)	:	DIL and FP outline rationalised	23442
		Figure 3(b)	:	Column heading rationalised	23442
			:	Inputs columns reversed	23442
			:	In Outputs column "Y" and "-Z" deleted	23442
		Figure 3(c)	:	Circuit 'A' drawing added from Figure 3(d) Circuit 'A'	23442
			:	Circuit 'A' heading and Circuit 'B' entry deleted	22398
		Figure 3(d)	:	Circuit 'A' drawing transferred to Figure 3(c) Circuit 'A'	23442
			:	Circuit 'A' heading, Circuit 'B' entry and Circuits 'A' and 'B' headings deleted	22398
		Figure 3(e)	:	Circuit 'A' heading and Circuit 'B' heading and drawing deleted	22398
		Para. 2	:	Document "(c)" deleted	21025
		Para. 4.4.2	:	PIND Test and Conditions added	22360
		Para. 4.5.2	:	Third sentence amended to read "...2(c)"	22398
		Tables 2, 3(a), (b)	:	Wherever applicable in Conditions column, ($\overline{E}$), (Y), (Z) replaced by "(Inhibit), (Channel I/O) and (Common O/I)" respectively	23442
			:	Nos. 29 to 44 and 45 to 60, Pins reversed	23442
			:	Nos 61 and 62, in Limits column, Circuit 'A' reference and Circuit 'B' reference and value deleted	23442
			:	Nos. 63 to 286 and 287 to 542, in Conditions "R_L = 10kΩ" added	23442
			:	No. 543, in Conditions column V_{IH} corrected to "5Vdc"	23442
			:	Nos. 543 and 544, Note number changed to "5" and all subsequent Note entries incremented by 1	23442
		Table 2	:	Nos. 547 to 551, Limits column amended	22398
			:	Nos. 552 to 556, "Circuit A" deleted from first measurement and "Circuit B" entry deleted in toto	22398
			:	Nos. 562 to 577, 578, 579, 580, 583, in Limits column, Circuit 'A' reference and Circuit 'B' reference and value deleted	23442

DOCUMENTATION CHANGE NOTICE

Rev. Letter	Rev. Date	Reference	CHANGE Item	Approved DCR No.
			: Nos. 579, 580, Figure number changed to "4(p)" and in Conditions "R_L = 10kΩ" added	23442
			: Nos. 581, 584, Figure number changed to "4(q)" and in Conditions "V_{IL} = 0Vdc, V_{IH} = 5Vdc and R_L = 200kΩ" added	23442
			: Nos. 582, 583, Figure number changed to "4(p)" and in Conditions "R_L = 300Ω" added	23442
			: No. 584, in Conditions, "V_{IN} (All other Channels) = 0Vdc" added	23442
		Tables 3(a), (b)	: No. 544, in Conditions, "V_{DD} = 15Vdc, V_{SS} = 0Vdc" added	23442
		Table 3(b)	: Nos. 287 to 542, V_{IH} and V_{DD} corrected to "15Vdc"	23442
		Figure 4(a)	: Note 2 corrected.	23442
			: In Note 3, "Ground" corrected to "V_{SS}"	23442
		Figure 4(b)	: In Note 2, "Ground" corrected to "V_{SS}"	23442
		Figures 4(c), (d)	: Figures corrected	23442
		Figure 4(e), (f)	: Figures rationalised	23442
		Figure 4(g), (i)	: Note 1 standardised	23442
		Figure 4(g) (ii), (iii)	: Figures rationalised	23442
		Figure 4(h)	: Figure corrected	23442
		Figure 4(i), (j)	: Input Conditions specified	23442
		Figure 4(l)	: Circuit 'A' heading and Circuit 'B' heading and drawing deleted	22398
		Figure 4(n), (o)	: Figures rationalised	23442
		Figure 4(p)	: Figure deleted	23442
		Figure 4(q)	: Figure renumbered to "4(p)"	23442
		Figure 4(r)	: Figure renumbered to "4(q)"	23442
		Figures 4(s), (t)	: Figures deleted	23442
		Tables 5(a), (b)	: Titles amended	23162
		Table 5(c)	: Nos. 2 and 3, Symbols corrected	23422
		Figure 5(a)	: Title amended	23162
			: Resistors added to each input at V_{DD}	23442
		Figure 5(b)	: Title amended	23162
			: Resistors added to each input at V_{SS}	23442
		Figure 5(c)	: Resistors added to each input at V_{DD} and V_{GEN}	23442
			: Pin 15 disconnected from Ground and connected to Binary counter	23442
			: On Binary Counter, "C" and "D" connections reversed	23442
		Paras. 4.8.4 and 4.8.5	: Reference to Table and Figure amended to "5(c)"	23442
		Table 6	: Nos. 61 and 62, in Limits column, Circuit 'A' reference and Circuit 'B' reference and value deleted	23442
'A'	March'92	P1. Cover page		None
		P2A. DCN		None
		P6. Table 1(a)	: Lead Material and/or Finish amended	23465
		P15. Para. 4.2.2	: Deviation deleted, "None" added	21048
		Para. 4.2.4	: Deviation deleted, "None" added	22919
		P16. Para. 4.2.5	: Deviation deleted, "None" added	22919
		Para. 4.4.2	: Material Type and Finishes amended	23465

DOCUMENTATION CHANGE NOTICE

Rev. Letter	Rev. Date	Reference	CHANGE Item	Approved DCR No.
'B'	Oct. '94	P1. Cover Page		None
		P2B. DCN	: Page added	None
		P6. Table 1(a)	: Lead Material and/or Finish amended	221049
		P16. Para. 4.3.2	: Weights amended	23539
		Para. 4.4.2	: Lead Finish, Types amended	221049
'A'	Apr. '01	P1. Cover Page	: Page count increased by 1	221602
		P2B. DCN		None
		P4. T of C	: Appendices entry amended	221602
		P5. Para. 1.3	: New sentence added	221602
		P6. Table 1(a)	: Variants 08 and 09 added	221562
		Table 1(b)	: No. 8, Maximum temperature amended	221562
		P9. Figure 2(c)	: In the drawing, Pin No. 28 location corrected	221550
		P10. Notes to Figures	: Title amended	221562
			: Note 1 rewritten	221562
		P10A. Figure 2(d)	: New page added	221562
		P11. Figure 3(a)	: Upper drawing Title amended	221562
		P12. Figure 3(a)	: "SO" added to comparison Titles	221562
		P16. Para. 4.3.2	: SO package added to the text	221562
		Para. 4.4.2	: SO package added to the text	221562
		Para. 4.5.2	: SO package added to the text	221562
		P59. Para. 4.8.6	: Last sentence deleted, new text added	221602
		P61. Appendix 'A'	: Appendix added	221602

TABLE OF CONTENTS

Page

TABLES

FIGURES

APPENDICES (Applicable to specific Manufacturers only)

1. GENERAL

1.1 SCOPE

This specification details the ratings, physical and electrical characteristics, test and inspection data for a silicon monolithic CMOS Analogue Multiplexer/Demultiplexer, having fully buffered outputs, based on Type 4067B. It shall be read in conjunction with ESA/SCC Generic Specification No. 9000, the requirements of which are supplemented herein.

1.2 COMPONENT TYPE VARIANTS

Variants of the basic type integrated circuits specified herein, which are also covered by this specification, are given in Table 1(a).

1.3 MAXIMUM RATINGS

The maximum ratings, which shall not be exceeded at any time during use or storage, applicable to the integrated circuits specified herein, are as scheduled in Table 1(b).

Maximum ratings shall only be exceeded during testing to the extent specified in this specification and when stipulated in Test Methods and Procedures of the applicable ESA/SCC Generic Specification.

1.4 PARAMETER DERATING INFORMATION (FIGURE 1)

Not applicable.

1.5 PHYSICAL DIMENSIONS

As per Figure 2.

1.6 PIN ASSIGNMENT

As per Figure 3(a).

1.7 TRUTH TABLE

As per Figure 3(b).

1.8 CIRCUIT SCHEMATIC

As per Figure 3(c).

1.9 FUNCTIONAL DIAGRAM

As per Figure 3(d).

1.10 HANDLING PRECAUTIONS

These devices are susceptible to damage by electrostatic discharge. Therefore, suitable precautions shall be employed for protection during all phases of manufacture, testing, packaging, shipment and any handling. These components are categorised as Class 1 with a Minimum Critical Path Failure Voltage of 400Volts.

1.11 INPUT PROTECTION NETWORK

Double diode protection shall be incorporated into each input as shown in Figure 3(e).

TABLE 1(a) - TYPE VARIANTS

VARIANT	CASE	FIGURE	LEAD MATERIAL AND/OR FINISH
01	FLAT	2(a)	G2 or G8
02	FLAT	2(a)	G4
03	D.I.L.	2(b)	G2 or G8
04	D.I.L.	2(b)	G4
07	CHIP CARRIER	2(c)	2
08	SO CERAMIC	2(d)	G2
09	SO CERAMIC	2(d)	G4

TABLE 1(b) - MAXIMUM RATINGS

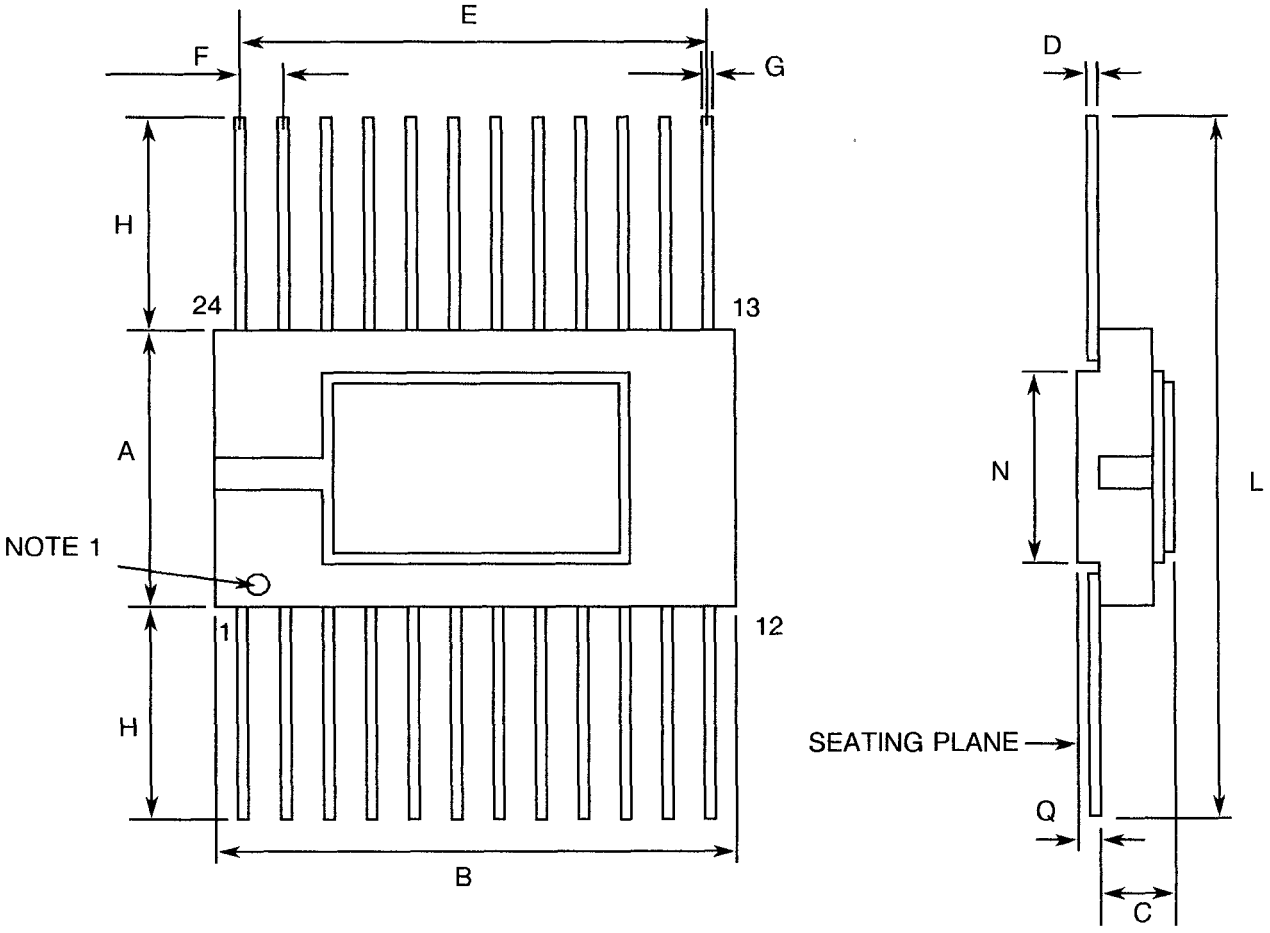
NO.	CHARACTERISTICS	SYMBOL	MAXIMUM RATINGS	UNIT	REMARKS (Note 8)
1	Supply Voltage	V_{DD}	-0.5 to +18	V	Note 1
2	Input Voltage	V_{IN}	-0.5 to V_{DD} + 0.5	V	Note 2 Power on
3	D.C. Input Current	$\pm I_{IN}$	10	mA	Note 3
4	D.C. Output Current	$\pm I_O$	10	mA	Note 4
5	Device Dissipation	P_D	200	mW	Per Package
6	Output Dissipation	P_{DSO}	100	mW	Note 5
7	Operating Temperature Range	T_{op}	-55 to +125	°C	-
8	Storage Temperature Range	T_{stg}	-65 to +150	°C	-
9	Soldering Temperature For FP and DIP For CCP	T_{sol}	+300 +245	°C	Note 6 Note 7

NOTES

1. Device is functional from +3V to +15V with reference to V_{SS}.
2. V_{DD} +0.5V should not exceed +18V.
3. Any one input.
4. The maximum output current of any single output.
5. The maximum power dissipation of any single output.
6. Duration 10 seconds maximum at a distance of not less than 1.5mm from the device body and the same lead shall not be resoldered until 3 minutes have elapsed.
7. Duration 30 seconds maximum and the same terminal shall not be resoldered until 3 minutes have elapsed.
8. When current is drawn from Common OUT/IN to Channel IN/OUT, the voltage drop across the bidirectional switch shall not exceed 0.4V.

FIGURE 2- PHYSICAL DIMENSIONS

FIGURE 2 (a) - FLAT PACKAGE, 24-PIN

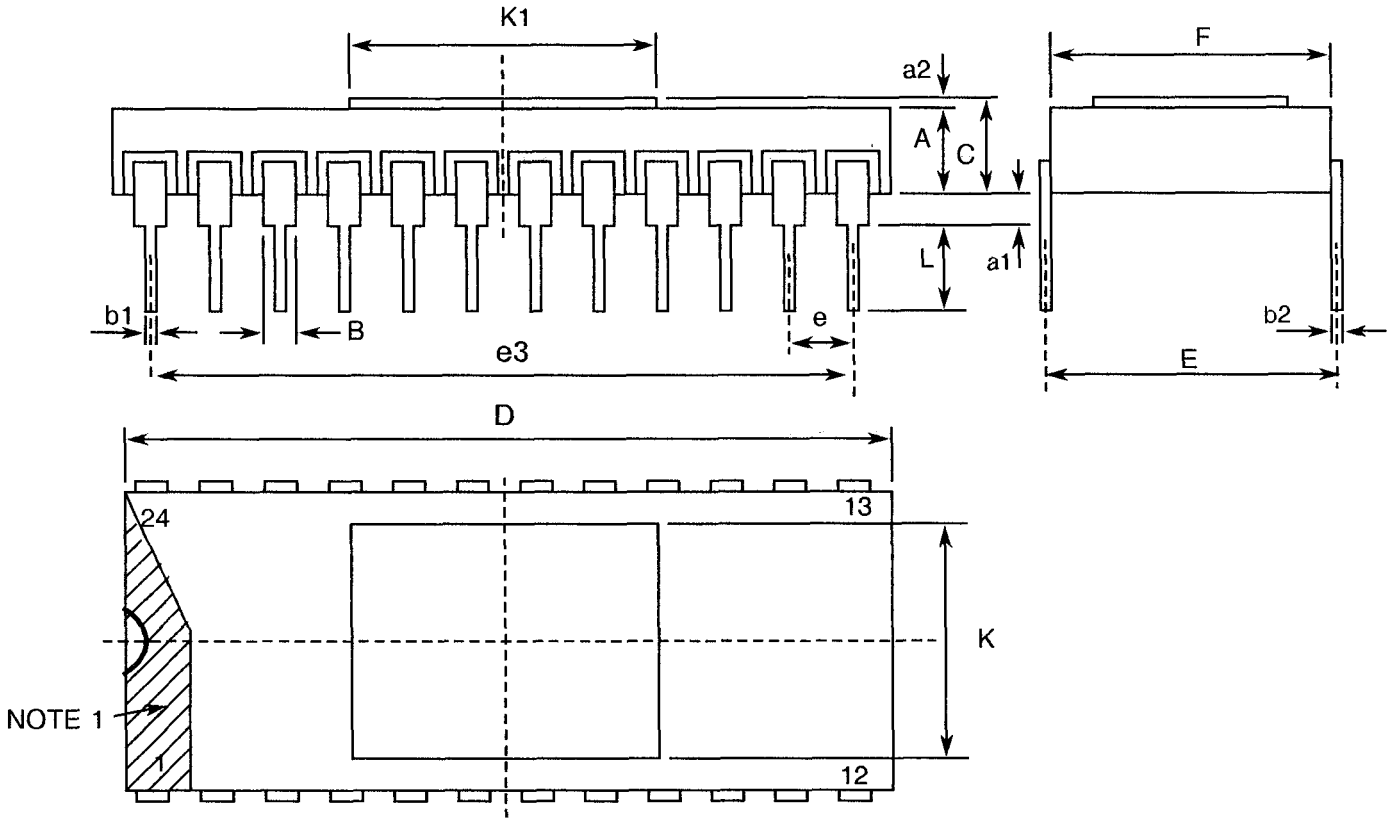


SYMBOL	MILLIMETRES		NOTES
	MIN	MAX	
A	10.70	11.30	
B	15.30	15.70	
C	1.45	1.90	
D	0.23	0.30	
E	13.84	14.10	
F	1.20	1.30	4
G	0.45	0.55	3
H	7.25	8.25	
L	25.00	28.00	
N	7.00	TYPICAL	
Q	0.45	0.55	2

NOTES: See Page 10.

FIGURE 2 - PHYSICAL DIMENSIONS (CONTINUED)

FIGURE 2 (b) - DUAL-IN-LINE PACKAGE, 24-PIN

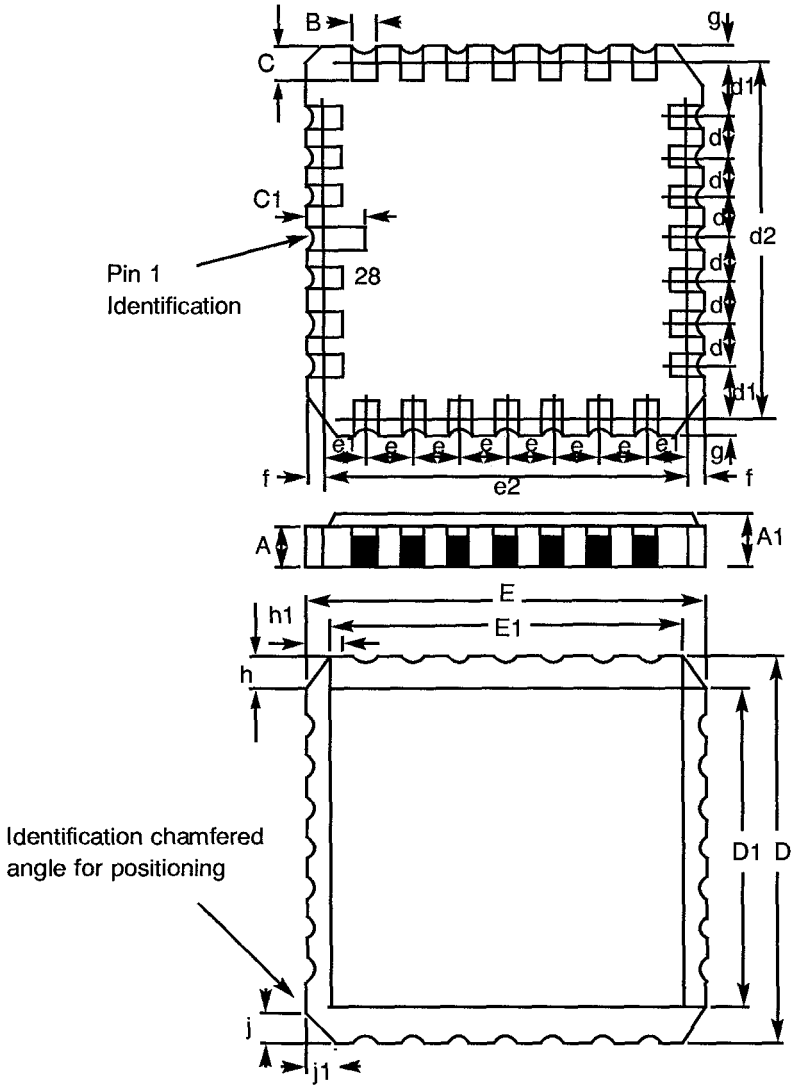


SYMBOL	MILLIMETRES		NOTES
	MIN	MAX	
A	1.931	2.387	
a_1	1.016	1.524	2
a_2	0.274	0.340	
B	1.274 TYPICAL		3
b_1	0.407	0.507	3
b_2	0.229	0.304	3
C	2.205	2.727	
D	30.784	30.784	
E	14.986	15.494	
e	2.413	2.667	4
e_3	27.813	28.067	
F	14.859	15.367	
L	3.0	3.8	
K	12.6	13.0	
k_1	12.6	13.0	

NOTES: See Page 10.

FIGURE 2 - PHYSICAL DIMENSIONS (CONTINUED)

FIGURE 2(c) - CHIP CARRIER - 28-TERMINAL



DIMENSIONS	MILLIMETRES		NOTES
	MIN	MAX	
A	1.14	1.95	
A1	1.63	2.36	
B	0.55	0.72	3
C	1.06	1.47	3
C_1	1.91	2.41	
D	8.67	9.09	
D1	7.21	7.52	
d, d1	1.27	TYPICAL	4
d2	7.62	TYPICAL	
E	8.67	9.09	
E1	7.21	7.52	
e, e1	1.27	TYPICAL	4
e2	7.62	TYPICAL	
f, g	-	0.76	
h, h1	1.01	TYPICAL	6
j, j1	0.51	TYPICAL	5

NOTES: See Page 10.

FIGURE 2 - PHYSICAL DIMENSIONS (CONTINUED)

NOTES TO FIGURES 2(a) TO 2(d) INCLUSIVE

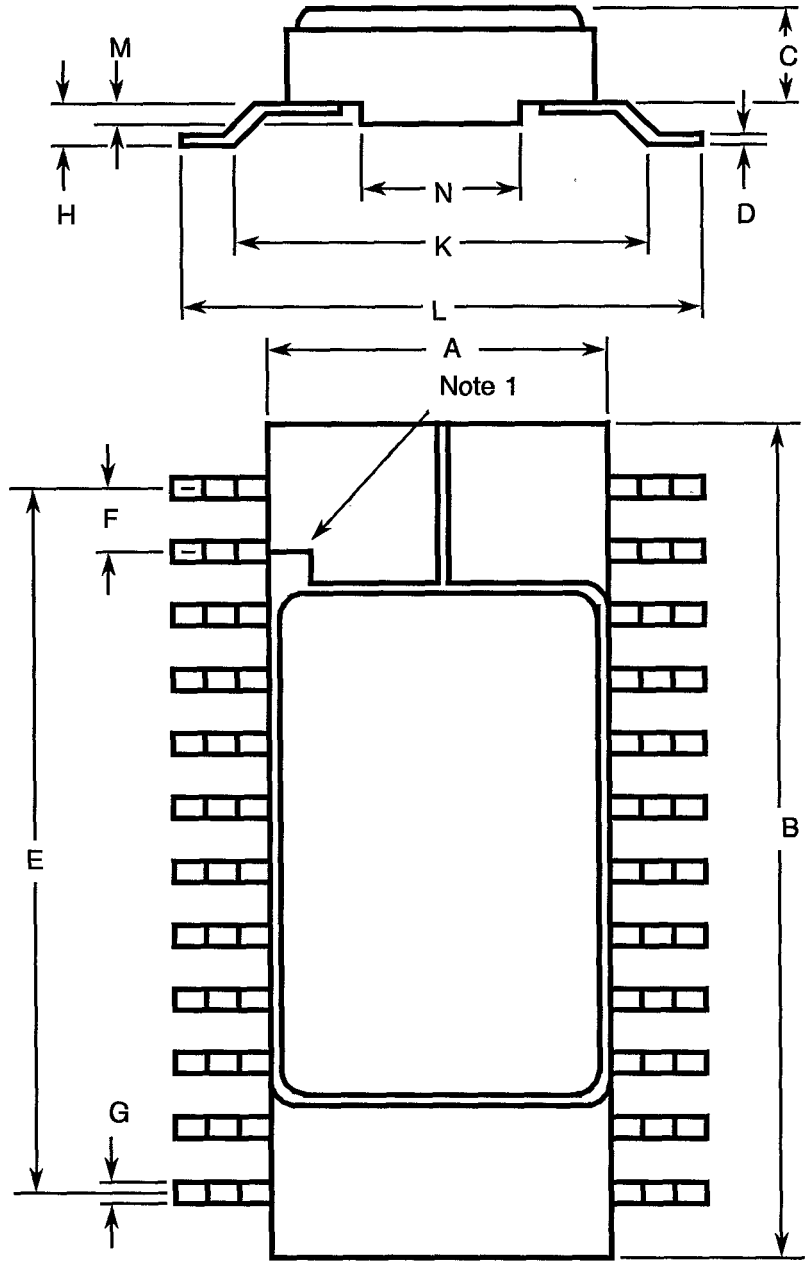
1. Index area: a notch, letter, metallised tab or dot shall be located adjacent to Pin 1 or 2 and shall be within the shaded area shown.

   For chip carrier packages the index shall be as defined in Figure 2(c).

   For SO packages, a dot shall also be located adjacent to Pin 1 on the bottom of the package.
2. The dimension shall be measured from the seating plane to the base plane.
3. All leads or terminals.
4. 24 pin packages : 22 spaces.
   28 terminal packages : 16 spaces.
5. Index corner only.
6. Three non-index corners.

FIGURE 2 - PHYSICAL DIMENSIONS (CONTINUED)

FIGURE 2(d) - SMALL OUTLINE CERAMIC PACKAGE, 24-PIN

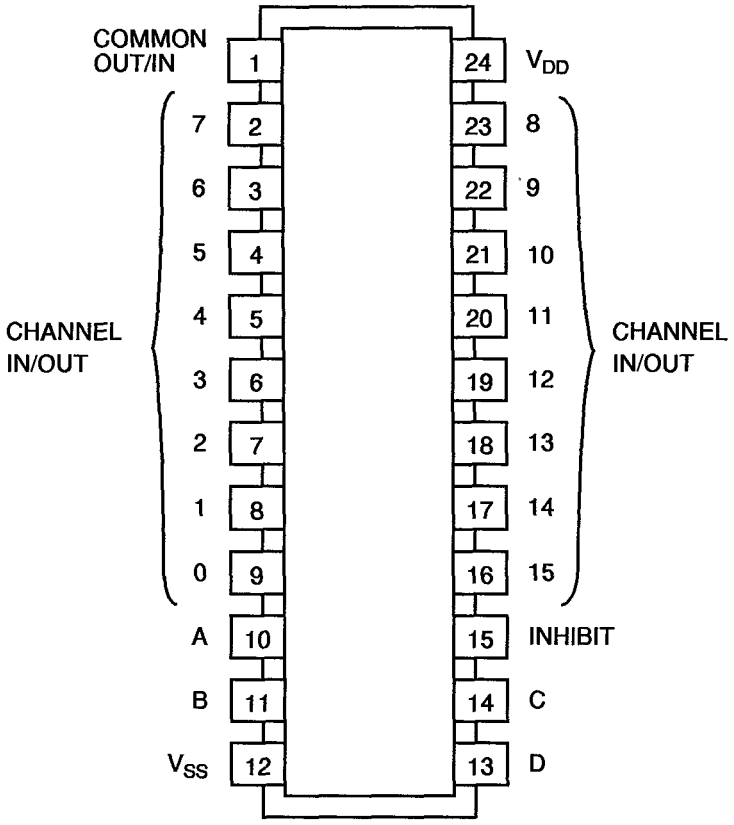


SYMBOL	MILLIMETRES		NOTES
	MIN.	MAX.	
A	7.30	7.60	
B	15.20	15.60	
C	1.58	1.88	
D	0.17	0.23	3
E	13.82	14.12	
F	1.27 TYPICAL		4
G	0.37	0.47	3
H	0.60	0.90	3
K	9.00 TYPICAL		
L	10	10.65	
M	0.55 TYPICAL		
N	4.31 TYPICAL		

NOTES: See Page 10.

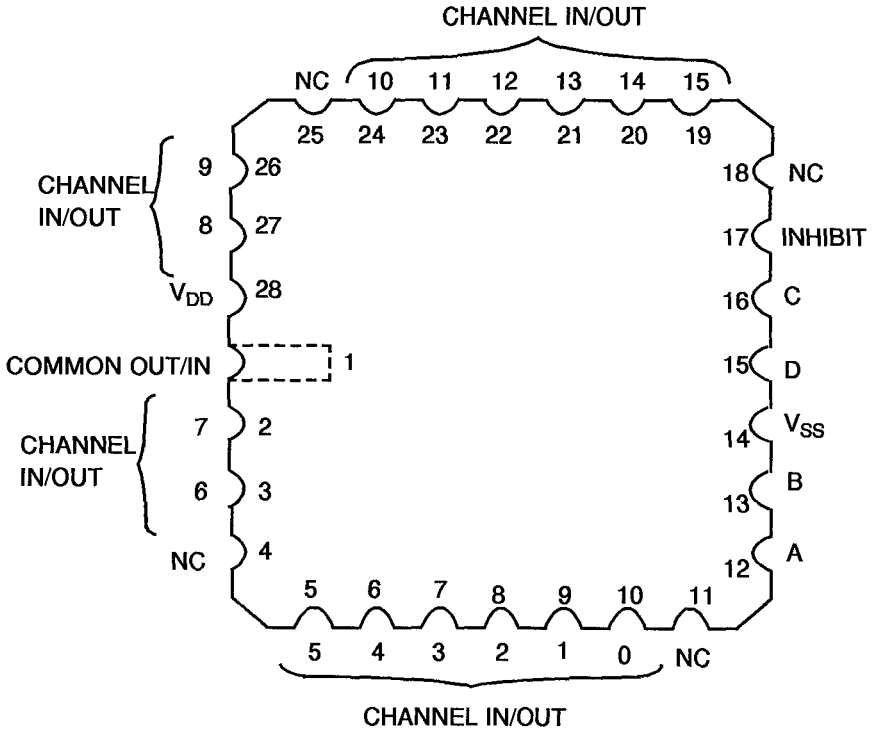
FIGURE 3(a) - PIN ASSIGNMENT

DUAL-IN-LINE, SO AND FLAT PACKAGES



TOP VIEW

CHIP CARRIER PACKAGE



TOP VIEW

FIGURE 3(a) - PIN ASSIGNMENT (CONTINUED)

FLAT PACKAGE, SO AND DUAL-IN-LINE TO CHIP CARRIER PIN ASSIGNMENT

FLAT PACKAGE, SO AND DUAL-IN-LINE PIN OUTS	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24
CHIP CARRIER PIN OUTS	1	2	3	5	6	7	8	9	10	12	13	14	15	16	17	19	20	21	22	23	24	26	27	28

FIGURE 3 (b) - TRUTH TABLE

INPUTS					SELECTED CHANNEL ON
INHIBIT	A	B	C	D	
L	L	L	L	L	0
L	H	L	L	L	1
L	L	H	L	L	2
L	H	H	L	L	3
L	L	L	H	L	4
L	H	L	H	L	5
L	L	H	H	L	6
L	H	H	H	L	7
L	L	L	L	H	8
L	H	L	L	H	9
L	L	H	L	H	10
L	H	H	L	H	11
L	L	L	H	H	12
L	H	L	H	H	13
L	L	H	H	H	14
L	H	H	H	H	15
H	X	X	X	X	NONE

NOTES

1. Logic Level Definitions: L = Low Level, H = High Level, X = Irrelevant.

FIGURE 3(c) - CIRCUIT SCHEMATIC

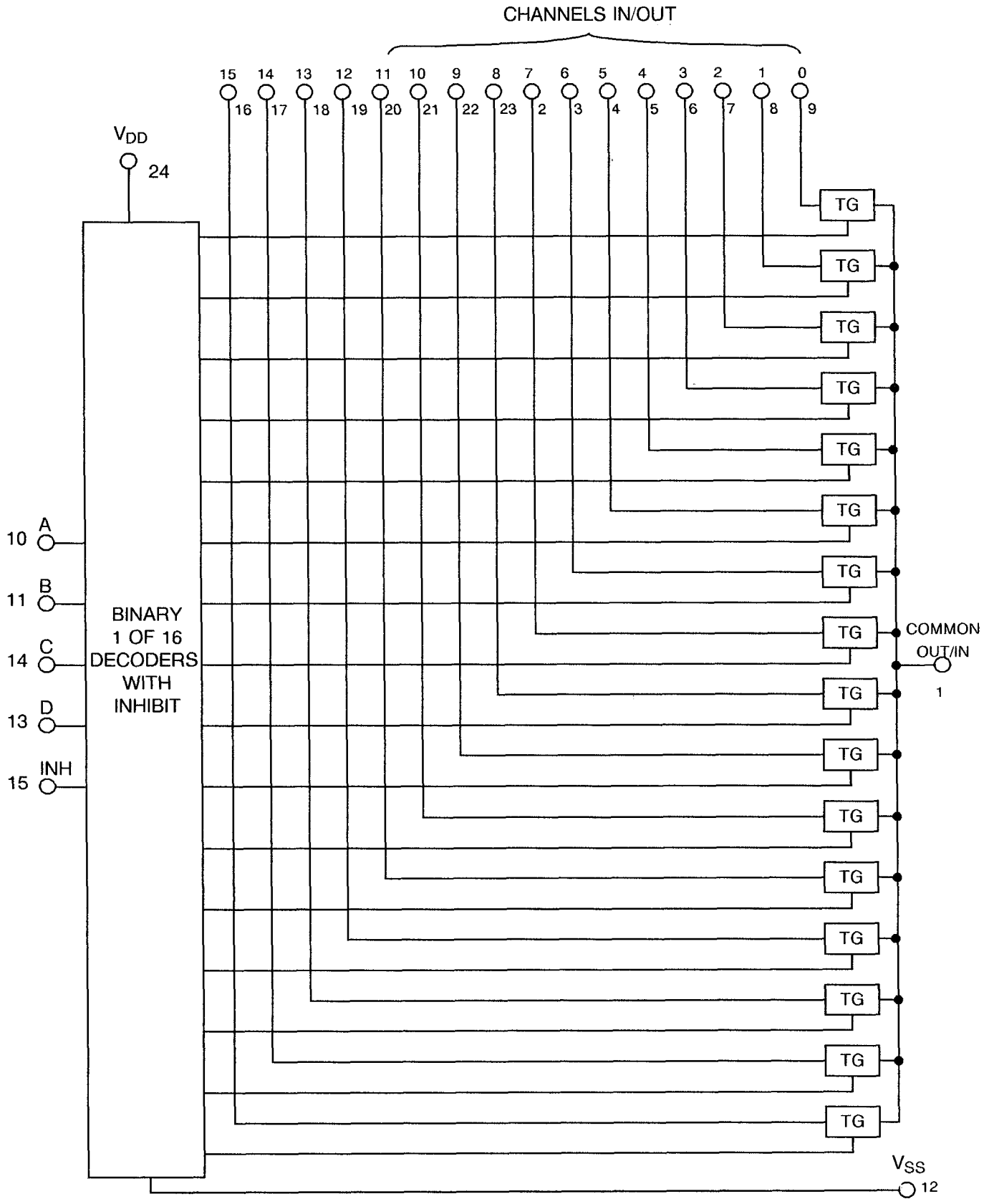


FIGURE 3(d) - FUNCTIONAL DIAGRAM

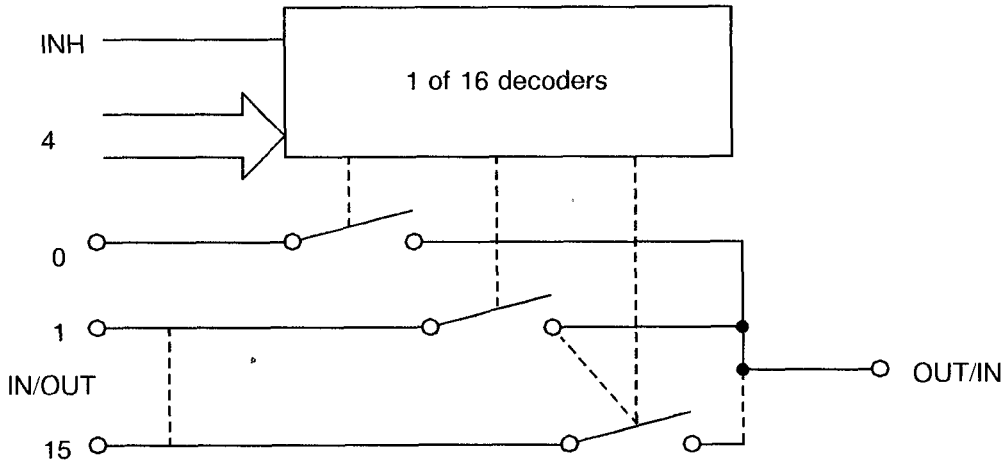
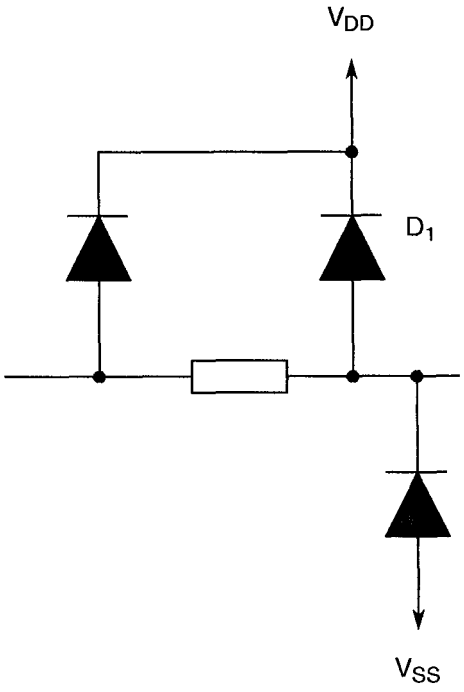


FIGURE 3 (e) - INPUT PROTECTION NETWORK



2. APPLICABLE DOCUMENTS

The following documents form part of this specification and shall be read in conjunction with it:-

(a) ESA/SCC Generic Specification No. 9000 for Integrated Circuits.

(b) MIL-STD-883, Test Methods and Procedures for Micro-electronics.

3. TERMS, DEFINITIONS, ABBREVIATIONS, SYMBOLS AND UNITS

For the purpose of this specification, the terms, definitions, abbreviations, symbols and units specified in ESA/SCC Basic Specification No. 21300 shall apply. In addition, the following abbreviations are used:

V_{IC} = Input Clamp Voltage
P_{DSO} = Single Output Power Dissipation
CKT = Circuit
I_{OFF} = Channel Off Leakage Current
R_{ON} = Channel On Resistance
C_{INC} = Channel Input Capacitance
C_{OC} = Channel Output Capacitance

4. REQUIREMENTS

4.1 GENERAL

The complete requirements for procurement of the integrated circuits specified herein are stated in this specification and ESA/SCC Generic Specification No. 9000 for Integrated Circuits. Deviations from the Generic Specification, applicable to this specification only, are listed in Para. 4.2.

Deviations from the applicable Generic Specification and this Detail Specification, formally agreed with specific Manufacturers on the basis that the alternative requirements are equivalant to the ESA/SCC requirement and do not affect the components' reliability, are listed in the appendices attached to this specification.

4.2 DEVIATIONS FROM GENERIC SPECIFICATION

4.2.1 Deviations from Special In-process Controls

None.

4.2.2 Deviations from Final Production Tests (Chart II)

None.

4.2.3 Deviations from Burn-in Tests (Chart III)

4.2.3.1 Deviations from High Temperature Reverse Bias (H.T.R.B.)

Prior to operating power burn-in, a high temperature reverse bias (H.T.R.B.) screen at +125°C shall be added for the N-Channel and then for the P-Channel in accordance with Tables 5(a) and 5(b) of this specification. Each exposure to H.T.R.B. shall be 72 hours and Table 4 Parameter Drift Values shall be applied at 0 and 144 hours.

4.2.4 Deviations from Qualification, Environmental and Endurance Tests (Chart IV)

None.

4.2.5 Deviations from Lot Acceptance Tests (Chart V)

None.

4.3 MECHANICAL REQUIREMENTS

4.3.1 Dimension Check

The dimensions of the integrated circuits specified herein shall be checked. They shall conform to those shown in Figure 2.

4.3.2 Weight

The maximum weight of the integrated circuits specified herein shall be 4.25 grammes for the dual-in-line package, 1.55 grammes for the flat package, 1.1 grammes for the SO package and 0.79 grammes for the chip carrier package.

4.4 MATERIALS AND FINISHES

The materials shall be as specified herein. Where a definite material is not specified, a material which will enable the integrated circuits specified herein to meet the performance requirements of this specification shall be used. Acceptance or approval of any constituent material does not guarantee acceptance of the finished product.

4.4.1 Case

The case shall be hermetically sealed and have a metal body with hard glass seals or a ceramic body and the lids shall be welded, brazed or preform-soldered.

4.4.2 Lead Material and Finish

For dual-in-line and flat packages, the material shall be Type 'G' with either Type '4' or Type '2 or 8' finish in accordance with ESA/SCC Basic Specification No. 23500. For chip carrier packages the finish shall be Type '2' in accordance with ESA/SCC Basic Specification No. 23500. For SO ceramic packages, the material shall be Type 'G' with either Type '2' or Type '4' finish in accordance with ESA/SCC Basic Specification No. 23500. (See Table 1(a) for Type Variants).

4.5 MARKING

4.5.1 General

The marking of all components delivered to this specification shall be in accordance with the requirements of ESA/SCC Basic Specification No. 21700. Each component shall be marked in respect of:-

(a) Lead Identification.

(b) The SCC Component Number.

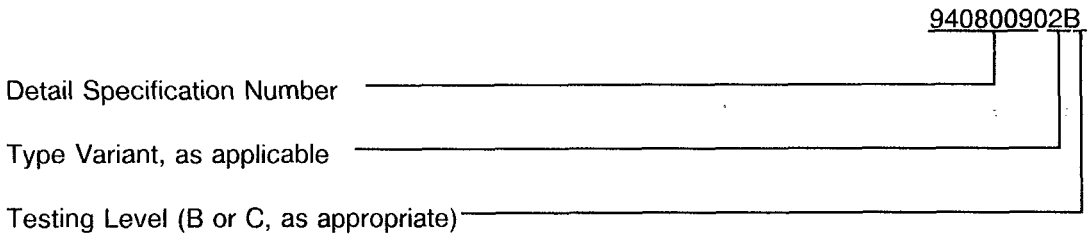
(c) Traceability Information.

4.5.2 Lead Identification

For dual-in-line, flat and SO packages, an index shall be located at the top of the package in the position defined in Note 1 to Figure 2 or, alternatively, a tab may be used to identify Pin No. 1. The pin numbering must be read with the index or tab on the left-hand side. For chip carrier packages, the index shall be as defined by Figure 2(c).

4.5.3 The SCC Component Number

Each component shall bear the SCC Component Number which shall be constituted and marked as follows:-



4.5.4 Traceability Information

Each component shall be marked in respect of traceability information in accordance with the requirements of ESA/SCC Basic Specification No. 21700.

4.6 ELECTRICAL MEASUREMENTS

4.6.1 Electrical Measurements at Room Temperature

The parameters to be measured in respect of electrical characteristics are scheduled in Table 2. Unless otherwise specified, the measurements shall be performed at T_{amb} = +22 ± 3 °C.

4.6.2 Electrical Measurements at High and Low Temperatures

The parameters to be measured at high and low temperatures are scheduled in Table 3. The measurements shall be performed at T_{amb} = +125(+0-5) °C and -55(+5-0) °C respectively.

4.6.3 Circuits for Electrical Measurements

Circuits and functional test sequence for use in performing electrical measurements listed in Tables 2 and 3 of this specification are shown in Figure 4.

4.7 BURN-IN TESTS

4.7.1 Parameter Drift Values

The parameter drift values applicable to burn-in are specified in Table 4 of this specification. Unless otherwise stated, measurements shall be performed at +22 ± 3 °C. The parameter drift values (Δ) applicable to the parameters scheduled, shall not be exceeded. In addition to these drift value requirements, the appropriate limit value specified for a given parameter in Table 2 shall not be exceeded.

4.7.2 Conditions for H.T.R.B. and Burn-in

The requirements for H.T.R.B. and Burn-in are specified in Section 7 of ESA/SCC Generic Specification No. 9000. The conditions for H.T.R.B. and Burn-in shall be as specified in Tables 5(a), 5(b) and 5(c) of this specification.

4.7.3 Electrical Circuits for H.T.R.B and Burn-in

Circuits for use in performing the H.T.R.B. and Burn-in tests are shown in Figures 5(a), 5(b) and 5(c) of this specification.

TABLE 2 - ELECTRICAL MEASUREMENTS AT ROOM TEMPERATURE - D.C. PARAMETERS

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS		UNIT
						MIN	MAX	
1	Functional Test	-	-	4 (a)	Verify Truth Table without Load. V_{DD} = 3Vdc, V_{SS} = 0Vdc Notes 1 and 2	-	-	-
2	Functional Test	-	-	4 (a)	Verify Truth Table without Load. V_{DD} = 15Vdc, V_{SS} = 0Vdc Notes 1 and 2	-	-	-
3 to 18	Quiescent Current	I_{DD}	3005	4 (b)	V_{IL} = 0Vdc, V_{IH} = 15Vdc V_{DD} = 15Vdc, V_{SS} = 0Vdc Note 3 (Pin D/F 24) (Pin C 28)	-	500	nA
19 to 23	Input Current Low Level Address or Inhibit	I_{IL}	3009	4 (c)	V_{IN} (Under Test) = 0Vdc V_{IN} (Other Inputs) = 15Vdc V_{DD} = 15Vdc, V_{SS} = 0Vdc (Pins D/F 10-11-13-14-15) (Pins C 12-13-15-16-17)	-	-50	nA
24 to 28	Input Current High Level Address or Inhibit	I_{IH}	3010	4 (d)	V_{IN} (Under Test) = 15Vdc V_{IN} (Other Inputs) = 0Vdc V_{DD} = 15Vdc, V_{SS} = 0Vdc (Pins D/F 10-11-13-14-15) (Pins C 12-13-15-16-17)	-	50	nA

NOTES: See Page 25.

TABLE 2 - ELECTRICAL MEASUREMENTS AT ROOM TEMPERATURE - D.C. PARAMETERS (CONT'D)

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS MIN	LIMITS MAX	UNIT
29 to 44	Channel Off Leakage Current (Any Channel)	I_{OFF1}	-	4 (e)	V_{IN} (INHIBIT) = 15Vdc V_{IN} (Address Inputs) = 0Vdc V_{IN} (CHANNEL I/O) = 15Vdc V_{IN} (COMMON O/I) = 0Vdc V_{DD} = 15Vdc, V_{SS} = 0Vdc Pins D/F — Pins C 2 to 1 — 2 to 1 3 to 1 — 3 to 1 4 to 1 — 5 to 1 5 to 1 — 6 to 1 6 to 1 — 7 to 1 7 to 1 — 8 to 1 8 to 1 — 9 to 1 9 to 1 — 10 to 1 16 to 1 — 19 to 1 17 to 1 — 20 to 1 18 to 1 — 21 to 1 19 to 1 — 22 to 1 20 to 1 — 23 to 1 21 to 1 — 24 to 1 22 to 1 — 26 to 1 23 to 1 — 27 to 1	-	-100	nA
45 to 60	Channel Off Leakage Current (Any Channel)	I_{OFF2}	-	4 (e)	V_{IN} (INHIBIT) = 15Vdc V_{IN} (Address Inputs) = 0Vdc V_{IN} (CHANNEL I/O) = 0Vdc V_{IN} (COMMON I/O) = 15Vdc V_{DD} = 15Vdc, V_{SS} = 0Vdc Pins D/F — Pins C 1 to 2 — 1 to 2 1 to 3 — 1 to 3 1 to 4 — 1 to 5 1 to 5 — 1 to 6 1 to 6 — 1 to 7 1 to 7 — 1 to 8 1 to 8 — 1 to 9 1 to 9 — 1 to 10 1 to 16 — 1 to 19 1 to 17 — 1 to 20 1 to 18 — 1 to 21 1 to 19 — 1 to 22 1 to 20 — 1 to 23 1 to 21 — 1 to 24 1 to 22 — 1 to 26 1 to 23 — 1 to 27	-	100	nA

NOTES: See Page 25.

TABLE 2 - ELECTRICAL MEASUREMENTS AT ROOM TEMPERATURE - D.C. PARAMETERS (CONT'D)

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS MIN	LIMITS MAX	UNIT
61	Channel Off Leakage Current (All Channels)	I_{OFF3}	-	4 (f)	V_{IN} (INHIBIT) = 15Vdc V_{IN} (Address Inputs) = 0Vdc V_{IN} (ALL CHANNEL I/O) = 0Vdc V_{IN} (COMMON O/I) = 15Vdc V_{DD} = 15Vdc, V_{SS} = 0Vdc Pins D/F — Pins C 1 to 2 — 1 to 2 1 to 3 — 1 to 3 1 to 4 — 1 to 5 1 to 5 — 1 to 6 1 to 6 — 1 to 7 1 to 7 — 1 to 8 1 to 8 — 1 to 9 1 to 9 — 1 to 10 1 to 16 — 1 to 19 1 to 17 — 1 to 20 1 to 18 — 1 to 21 1 to 19 — 1 to 22 1 to 20 — 1 to 23 1 to 21 — 1 to 24 1 to 22 — 1 to 26 1 to 23 — 1 to 27	-	100	nA
62	Channel Off Leakage Current (All Channels)	I_{OFF4}	-	4 (f)	V_{IN} (INHIBIT) = 15Vdc V_{IN} (Address Inputs) = 0Vdc V_{IN} (ALL CHANNEL I/O) = 15Vdc V_{IN} (COMMON I/O) = 0Vdc V_{DD} = 15Vdc, V_{SS} = 0Vdc Pins D/F — Pins C 2 to 1 — 2 to 1 3 to 1 — 3 to 1 4 to 1 — 5 to 1 5 to 1 — 6 to 1 6 to 1 — 7 to 1 7 to 1 — 8 to 1 8 to 1 — 9 to 1 9 to 1 — 10 to 1 16 to 1 — 19 to 1 17 to 1 — 20 to 1 18 to 1 — 21 to 1 19 to 1 — 22 to 1 20 to 1 — 23 to 1 21 to 1 — 24 to 1 22 to 1 — 26 to 1 23 to 1 — 27 to 1	-	-100	nA

NOTES: See Page 25.

TABLE 2 - ELECTRICAL MEASUREMENTS AT ROOM TEMPERATURE - D.C. PARAMETERS (CONT'D)

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS		UNIT
						MIN	MAX	
63 to 286	Channel On Resistance	R_{ON1}	-	4 (g)	V_{IN} (INHIBIT) = 0Vdc V_{IN} (Address Inputs): V_{IL} = 0Vdc, V_{IH} = 5Vdc I_{IN} = 100µAdc, R_L = 10kΩ Channel Input Conditions: See Test Table Figure 4(g)(i). V_{DD} = 5Vdc, V_{SS} = 0Vdc Note 4 Pins D/F — Pins C 1 to 2 — 1 to 2 1 to 3 — 1 to 3 1 to 4 — 1 to 5 1 to 5 — 1 to 6 1 to 6 — 1 to 7 1 to 7 — 1 to 8 1 to 8 — 1 to 9 1 to 9 — 1 to 10 1 to 16 — 1 to 19 1 to 17 — 1 to 20 1 to 18 — 1 to 21 1 to 19 — 1 to 22 1 to 20 — 1 to 23 1 to 21 — 1 to 24 1 to 22 — 1 to 26 1 to 23 — 1 to 27 2 to 1 — 2 to 1 3 to 1 — 3 to 1 4 to 1 — 5 to 1 5 to 1 — 6 to 1 6 to 1 — 7 to 1 7 to 1 — 8 to 1 8 to 1 — 9 to 1 9 to 1 — 10 to 1 16 to 1 — 19 to 1 17 to 1 — 20 to 1 18 to 1 — 21 to 1 19 to 1 — 22 to 1 20 to 1 — 23 to 1 21 to 1 — 24 to 1 22 to 1 — 26 to 1 23 to 1 — 27 to 1	-	1050	Ω

NOTES: See Page 25.

TABLE 2 - ELECTRICAL MEASUREMENTS AT ROOM TEMPERATURE - D.C. PARAMETERS (CONT'D)

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS		UNIT
						MIN	MAX	
287 to 542	Channel On Resistance	R_{ON2}	-	4 (g)	V_{IN} (INHIBIT) = 0Vdc V_{IN} (Address Inputs): V_{IL} = 0Vdc, V_{IH} = 15Vdc I_{IN} = 100µAdc, R_L = 10kΩ Channel Input Conditions: See Test Table Figure 4(g)(i). V_{DD} = 15Vdc, V_{SS} = 0Vdc Note 4	-	240	Ω

Pins D/F	Pins C
1 to 2	1 to 2
1 to 3	1 to 3
1 to 4	1 to 5
1 to 5	1 to 6
1 to 6	1 to 7
1 to 7	1 to 8
1 to 8	1 to 9
1 to 9	1 to 10
1 to 16	1 to 19
1 to 17	1 to 20
1 to 18	1 to 21
1 to 19	1 to 22
1 to 20	1 to 23
1 to 21	1 to 24
1 to 22	1 to 26
1 to 23	1 to 27
2 to 1	2 to 1
3 to 1	3 to 1
4 to 1	5 to 1
5 to 1	6 to 1
6 to 1	7 to 1
7 to 1	8 to 1
8 to 1	9 to 1
9 to 1	10 to 1
16 to 1	19 to 1
17 to 1	20 to 1
18 to 1	21 to 1
19 to 1	22 to 1
20 to 1	23 to 1
21 to 1	24 to 1
22 to 1	26 to 1
23 to 1	27 to 1

NOTES: See Page 25.

TABLE 2 - ELECTRICAL MEASUREMENTS AT ROOM TEMPERATURE - D.C. PARAMETERS (CONT'D)

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS MIN	LIMITS MAX	UNIT
543	Input Voltage Low Level (Noise Immunity) (Functional Test)	V_{IL1}	-	4 (h)	Address and Inhibit Inputs: V_{IL} = 1.5Vdc, V_{IH} = 3.5Vdc Channel Inputs: V_{IL} = 0Vdc, V_{IH} = 5Vdc V_{DD} = 5Vdc, V_{SS} = 0Vdc Note 5 (Pins D/F 2-3-4-5-6-7-8-9-16-17-18-19-20-21-22-23) (Pins C 2-3-5-6-7-8-9-10-19-21-22-23-24-26-27)	-	0.5	V
	Input Voltage High Level (Noise Immunity) (Functional Test)	V_{IH1}				4.5	-	
544	Input Voltage Low Level (Noise Immunity) (Functional Test)	V_{IL2}	-	4 (h)	Address and Inhibit Inputs: V_{IL} = 4Vdc, V_{IH} = 11Vdc Channel Inputs: V_{IL} = 0Vdc, V_{IH} = 15Vdc V_{DD} = 15Vdc, V_{SS} = 0Vdc Note 5 (Pins D/F 2-3-4-5-6-7-8-9-16-17-18-19-20-21-22-23) (Pins C 2-3-5-6-7-8-9-10-19-21-22-23-24-26-27)	-	1.5	V
	Input Voltage High Level (Noise Immunity) (Functional Test)	V_{IH2}				13.5	-	
545	Threshold Voltage N-Channel	V_{THN}	-	4 (i)	Inhibit Input at Ground. All Other Inputs: V_{IN} = 5Vdc V_{DD} = 5Vdc, I_{SS} = -10µA (Pin D/F 12) (Pin C 14)	-0.7	-3.0	V
546	Threshold Voltage P-Channel	V_{THP}	-	4 (j)	Inhibit Input at Ground. All Other Inputs: V_{IN} = -5Vdc V_{SS} = -5Vdc, I_{DD} = 10µA (Pin D/F 24) (Pin C 28)	0.7	3.0	V
547 to 551	Input Clamp Voltage (to V_{SS})	V_{IC1}	-	4 (k)	I_{IN} (Under Test) = -100µA V_{DD} = Open, V_{SS} = 0Vdc All Other Pins Open (Pins D/F 10-11-13-14-15) (Pins C 12-13-15-16-17)	-	-2.0	V
552 to 556	Input ClampVoltage (to V_{DD})	V_{IC2}	-	4 (l)	V_{IN} (Under Test) = 6Vdc V_{SS} = Open, R = 30kΩ (Pins D/F 10-11-13-14-15) (Pins C 12-13-15-16-17)	3.0	-	V

NOTES: See Page 25.

TABLE 2 - ELECTRICAL MEASUREMENTS AT ROOM TEMPERATURE - A.C. PARAMETERS

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS		UNIT
						MIN	MAX	
557 to 561	Input Capacitance Address or Inhibit	C_{IN}	3012	4 (m)	V_{IN} (Not under Test) = 0Vdc V_{DD} = V_{SS} = 0Vdc Note 6 (Pins D/F 10-11-13-14-15) (Pins C 12-13-15-16-17)	-	7.5	pF
562 to 577	Channel Capacitance (Input)	C_{INC}	3012	4 (n)	V_{DD} = V_{SS} = 0Vdc Note 6 (Pins D/F 2-3-4-5-6-7-8-9-16-17-18-19-20-21-22-23) (Pins C 2-3-5-6-7-8-9-10-19-20-21-22-23-24-26-27)	-	7.5	pF
578	Channel Capacitance (Output)	C_{OC}	3012	4 (o)	V_{DD} = V_{SS} = 0Vdc Note 6 (Pin D/F 1) (Pin C 1)	-	120	pF
579	Propagation Delay Address to Signal OUT (Channel turning ON)	t_{PLH1}	3003	4 (p)	V_{IN} (Under Test) = Pulse Generator V_{IL} = 0Vdc, V_{IH} = 5Vdc R_L = 10kΩ V_{DD} = 5Vdc, V_{SS} = 0Vdc Note 7 Pins D/F: 10 to 1 — Pins C: 12 to 1	-	650	ns
580	Propagation Delay Inhibit to Signal OUT (Channel turning ON)	t_{PLH2}	3003	4 (p)	V_{IN} (Under Test) = Pulse Generator V_{IL} = 0Vdc, V_{IH} = 5Vdc R_L = 10kΩ V_{DD} = 5Vdc, V_{SS} = 0Vdc Note 7 Pins D/F: 15 to 1 — Pins C: 17 to 1	-	650	ns
581	Propagation Delay Channel Input to Channel Output	t_{PLH3}	3003	4 (q)	V_{IN} (Under Test) = Pulse Generator V_{IL} = 0Vdc, V_{IH} = 5Vdc V_{IN} (All other channels) = 0Vdc R_L = 200kΩ V_{DD} = 5Vdc, V_{SS} = 0Vdc Note 7 Pins D/F: 9 to 1 — Pins C: 10 to 1	-	60	ns

NOTES: See Page 25.

TABLE 2 - ELECTRICAL MEASUREMENTS AT ROOM TEMPERATURE - A.C. PARAMETERS (CONT'D)

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS		UNIT
						MIN	MAX	
582	Propagation Delay Address to Signal OUT (Channel turning OFF)	t_{PHL1}	3003	4 (p)	V_{IN} (Under Test) = Pulse Generator V_{IL} = 0Vdc, V_{IH} = 5Vdc R_L = 300Ω V_{DD} = 5Vdc, V_{SS} = 0Vdc Note 7 Pins D/F: 10 to 1 Pins C: 12 to 1	-	440	ns
583	Propagation Delay Inhibit to Signal OUT (Channel turning OFF)	t_{PHL2}	3003	4 (p)	V_{IN} (Under Test) = Pulse Generator V_{IL} = 0Vdc, V_{IH} = 5Vdc R_L = 300Ω V_{DD} = 5Vdc, V_{SS} = 0Vdc Note 7 Pins D/F: 15 to 1 Pins C: 17 to 1	-	440	ns
584	Propagation Delay Channel Input to Channel Output	t_{PHL3}	3003	4 (q)	V_{IN} (Under Test) = Pulse Generator V_{IL} = 0Vdc, V_{IH} = 5Vdc V_{IN} (All other channels) = 0Vdc R_L = 200kΩ V_{DD} = 5Vdc, V_{SS} = 0Vdc Note 7 Pins D/F: 9 to 1 Pins C: 10 to 1	-	60	ns

NOTES

1. GO-NO-GO Test, each pattern of Test Table 4(a).

   $VOH \geq VDD - 0.5V$ $VOL \leq 0.5V$

2. Maximum time to output comparator strobe 300µsec.
3. Measure each value of IDD for the input conditions given in Table 4(b).
4. For characterisation during qualification, the incremental method or the method shown in Figure 4(g)(ii), which incorporates a plotter, shall apply. For procurement, the Orderer may accept that the devices are tested go-no-go to the maximum limits of Table 2. In the case that go-no-go testing is performed, it is necessary that at least one discrete value shall be measured and recordered in order that drift values may be applied. Figure 4(g)(iii) shall be used for the discrete value measurement.
5. This is performed as a Functional Test in which extreme VIN conditions are applied and output voltage is measured.
6. Measurement performed on a sample basis LTPD 7, or less, with a Capacitance Bridge connected between each input under test and VSS, only for Lots where LAT Level 2 is to be performed. (For LTPD sampling plan, see Annexe I of ESA/SCC 9000).
7. Measurement performed on a sample basis, LTPD 7 or less, (see Annexe I of ESA/SCC 9000).

TABLE 3(a) - ELECTRICAL MEASUREMENTS AT HIGH TEMPERATURE, + 125(+ 0 – 5) °C

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS		UNIT
						MIN	MAX	
1	Functional Test	-	-	4 (a)	Verify Truth Table without Load. V_{DD} = 3Vdc, V_{SS} = 0Vdc Notes 1 and 2	-	-	-
2	Functional Test	-	-	4 (a)	Verify Truth Table without Load. V_{DD} = 15Vdc, V_{SS} = 0Vdc Notes 1 and 2	-	-	-
3 to 18	Quiescent Current	I_{DD}	3005	4 (b)	V_{IL} = 0Vdc, V_{IH} = 15Vdc V_{DD} = 15Vdc, V_{SS} = 0Vdc Note 3 (Pin D/F 24) (Pin C 28)	-	15	µA
19 to 23	Input Current Low Level Address or Inhibit	I_{IL}	3009	4 (c)	V_{IN} (Under Test) = 0Vdc V_{IN} (Other Inputs) = 15Vdc V_{DD} = 15Vdc, V_{SS} = 0Vdc (Pins D/F 10-11-13-14-15) (Pins C 12-13-15-16-17)	-	-100	nA
24 to 28	Input Current High Level Address or Inhibit	I_{IH}	3010	4 (d)	V_{IN} (Under Test) = 15Vdc V_{IN} (Other Inputs) = 0Vdc V_{DD} = 15Vdc, V_{SS} = 0Vdc (Pins D/F 10-11-13-14-15) (Pins C 12-13-15-16-17)	-	100	nA

NOTES: See Page 25.

TABLE 3(a) - ELECTRICAL MEASUREMENTS AT HIGH TEMPERATURE, + 125(+ 0 – 5) °C (CONT'D)

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS MIN	LIMITS MAX	UNIT
29 to 44	Channel Off Leakage Current (Any Channel)	I_{OFF1}	-	4 (e)	V_{IN} (INHIBIT) = 15Vdc V_{IN} (Address Inputs) = 0Vdc V_{IN} (CHANNEL I/O) = 15Vdc V_{IN} (COMMON O/I) = 0Vdc V_{DD} = 15Vdc, V_{SS} = 0Vdc Pins D/F — Pins C 2 to 1 — 2 to 1 3 to 1 — 3 to 1 4 to 1 — 5 to 1 5 to 1 — 6 to 1 6 to 1 — 7 to 1 7 to 1 — 8 to 1 8 to 1 — 9 to 1 9 to 1 — 10 to 1 16 to 1 — 19 to 1 17 to 1 — 20 to 1 18 to 1 — 21 to 1 19 to 1 — 22 to 1 20 to 1 — 23 to 1 21 to 1 — 24 to 1 22 to 1 — 26 to 1 23 to 1 — 27 to 1	-	-1.0	µA
45 to 60	Channel Off Leakage Current (Any Channel)	I_{OFF2}	-	4 (e)	V_{IN} (INHIBIT) = 15Vdc V_{IN} (Address Inputs) = 0Vdc V_{IN} (CHANNEL I/O) = 0Vdc V_{IN} (COMMON I/O) = 15Vdc V_{DD} = 15Vdc, V_{SS} = 0Vdc Pins D/F — Pins C 1 to 2 — 1 to 2 1 to 3 — 1 to 3 1 to 4 — 1 to 5 1 to 5 — 1 to 6 1 to 6 — 1 to 7 1 to 7 — 1 to 8 1 to 8 — 1 to 9 1 to 9 — 1 to 10 1 to 16 — 1 to 19 1 to 17 — 1 to 20 1 to 18 — 1 to 21 1 to 19 — 1 to 22 1 to 20 — 1 to 23 1 to 21 — 1 to 24 1 to 22 — 1 to 26 1 to 23 — 1 to 27	-	1.0	µA

NOTES: See Page 25.

TABLE 3(a) - ELECTRICAL MEASUREMENTS AT HIGH TEMPERATURE, + 125(+ 0 – 5) °C (CONT'D)

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS MIN	LIMITS MAX	UNIT
61	Channel Off Leakage Current (All Channels)	I_{OFF3}	-	4 (f)	V_{IN} (INHIBIT) = 15Vdc V_{IN} (Address Inputs) = 0Vdc V_{IN} (ALL CHANNEL I/O) = 0Vdc V_{IN} (COMMON O/I) = 15Vdc V_{DD} = 15Vdc, V_{SS} = 0Vdc Pins D/F — Pins C 1 to 2 — 1 to 2 1 to 3 — 1 to 3 1 to 4 — 1 to 5 1 to 5 — 1 to 6 1 to 6 — 1 to 7 1 to 7 — 1 to 8 1 to 8 — 1 to 9 1 to 9 — 1 to 10 1 to 16 — 1 to 19 1 to 17 — 1 to 20 1 to 18 — 1 to 21 1 to 19 — 1 to 22 1 to 20 — 1 to 23 1 to 21 — 1 to 24 1 to 22 — 1 to 26 1 to 23 — 1 to 27	-	1.0	µA
62	Channel Off Leakage Current (All Channels)	I_{OFF4}	-	4 (f)	V_{IN} (INHIBIT) = 15Vdc $_{IN}$ (Address Inputs) = 0Vdc V_{IN} (ALL CHANNEL I/O) = 15Vdc V_{IN} (COMMON I/O) = 0Vdc V_{DD} = 15Vdc, V_{SS} = 0Vdc Pins D/F — Pins C 2 to 1 — 2 to 1 3 to 1 — 3 to 1 4 to 1 — 5 to 1 5 to 1 — 6 to 1 6 to 1 — 7 to 1 7 to 1 — 8 to 1 8 to 1 — 9 to 1 9 to 1 — 10 to 1 16 to 1 — 19 to 1 17 to 1 — 20 to 1 18 to 1 — 21 to 1 19 to 1 — 22 to 1 20 to 1 — 23 to 1 21 to 1 — 24 to 1 22 to 1 — 26 to 1 23 to 1 — 27 to 1	-	-1.0	µA

NOTES: See Page 25.

TABLE 3(a) - ELECTRICAL MEASUREMENTS AT HIGH TEMPERATURE, + 125(+ 0 – 5) °C (CONT'D)

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS		UNIT
						MIN	MAX	
63 to 286	Channel On Resistance	R_{ON1}	-	4 (g)	V_{IN} (INHIBIT) = 0Vdc V_{IN} (Address Inputs): V_{IL} = 0Vdc, V_{IH} = 5Vdc I_{IN} = 100µAdc, R_L = 10kΩ Channel Input Conditions: See Test Table Figure 4(g)(i). V_{DD} = 5Vdc, V_{SS} = 0Vdc Note 4	-	1300	Ω

Pins D/F	Pins C
1 to 2	1 to 2
1 to 3	1 to 3
1 to 4	1 to 5
1 to 5	1 to 6
1 to 6	1 to 7
1 to 7	1 to 8
1 to 8	1 to 9
1 to 9	1 to 10
1 to 16	1 to 19
1 to 17	1 to 20
1 to 18	1 to 21
1 to 19	1 to 22
1 to 20	1 to 23
1 to 21	1 to 24
1 to 22	1 to 26
1 to 23	1 to 27
2 to 1	2 to 1
3 to 1	3 to 1
4 to 1	5 to 1
5 to 1	6 to 1
6 to 1	7 to 1
7 to 1	8 to 1
8 to 1	9 to 1
9 to 1	10 to 1
16 to 1	19 to 1
17 to 1	20 to 1
18 to 1	21 to 1
19 to 1	22 to 1
20 to 1	23 to 1
21 to 1	24 to 1
22 to 1	26 to 1
23 to 1	27 to 1

NOTES: See Page 25.

TABLE 3(a) - ELECTRICAL MEASUREMENTS AT HIGH TEMPERATURE, +125(+0-5) °C (CONT'D)

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS		UNIT
						MIN	MAX	
287 to 542	Channel On Resistance	R_{ON2}	-	4 (g)	V_{IN} (INHIBIT) = 0Vdc V_{IN} (Address Inputs): V_{IL} = 0Vdc, V_{IH} = 15Vdc I_{IN} = 100µAdc, R_L = 10kΩ Channel Input Conditions: See Test Table Figure 4(g)(i). V_{DD} = 15Vdc, V_{SS} = 0Vdc Note 4	-	320	Ω

Pins D/F	Pins C
1 to 2	1 to 2
1 to 3	1 to 3
1 to 4	1 to 5
1 to 5	1 to 6
1 to 6	1 to 7
1 to 7	1 to 8
1 to 8	1 to 9
1 to 9	1 to 10
1 to 16	1 to 19
1 to 17	1 to 20
1 to 18	1 to 21
1 to 19	1 to 22
1 to 20	1 to 23
1 to 21	1 to 24
1 to 22	1 to 26
1 to 23	1 to 27
2 to 1	2 to 1
3 to 1	3 to 1
4 to 1	5 to 1
5 to 1	6 to 1
6 to 1	7 to 1
7 to 1	8 to 1
8 to 1	9 to 1
9 to 1	10 to 1
16 to 1	19 to 1
17 to 1	20 to 1
18 to 1	21 to 1
19 to 1	22 to 1
20 to 1	23 to 1
21 to 1	24 to 1
22 to 1	26 to 1
23 to 1	27 to 1

NOTES: See Page 25.

TABLE 3(a) - ELECTRICAL MEASUREMENTS AT HIGH TEMPERATURE, + 125(+ 0 – 5) °C (CONT'D)

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS MIN	LIMITS MAX	UNIT
543	Input Voltage Low Level (Noise Immunity) (Functional Test)	V_{IL1}	-	4 (h)	Address and Inhibit Inputs: V_{IL} = 1.5Vdc, V_{IH} = 3.5Vdc Channel Inputs: V_{IL} = 0Vdc, V_{IH} = 5Vdc V_{DD} = 5Vdc, V_{SS} = 0Vdc Note 5 (Pins D/F 2-3-4-5-6-7-8-9-16-17-18-19-20-21-22-23) (Pins C 2-3-5-6-7-8-9-10-19-21-22-23-24-26-27)	-	0.5	V
	Input Voltage High Level (Noise Immunity) (Functional Test)	V_{IH1}				4.5	-	
544	Input Voltage Low Level (Noise Immunity) (Functional Test)	V_{IL2}	-	4 (h)	Address and Inhibit Inputs: V_{IL} = 4Vdc, V_{IH} = 11Vdc Channel Inputs: V_{IL} = 0Vdc, V_{IH} = 15Vdc V_{DD} = 15Vdc, V_{SS} = 0Vdc Note 5 (Pins D/F 2-3-4-5-6-7-8-9-16-17-18-19-20-21-22-23) (Pins C 2-3-5-6-7-8-9-10-19-21-22-23-24-26-27)	-	1.5	V
	Input Voltage High Level (Noise Immunity) (Functional Test)	V_{IH2}				13.5	-	
545	Threshold Voltage N-Channel	V_{THN}	-	4 (i)	Inhibit Input at Ground. All Other Inputs: V_{IN} = 5Vdc V_{DD} = 5Vdc, I_{SS} = -10µA (Pin D/F 12) (Pin C 14)	-0.3	-3.5	V
546	Threshold Voltage P-Channel	V_{THP}	-	4 (j)	Inhibit Input at Ground. All Other Inputs: V_{IN} = -5Vdc V_{SS} = -5Vdc, I_{DD} = 10µA (Pin D/F 24) (Pin C 28)	0.3	3.5	V

NOTES: See Page 25.

TABLE 3(b) - ELECTRICAL MEASUREMENTS AT LOW TEMPERATURE, – 55(+5–0) °C

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS		UNIT
						MIN	MAX	
1	Functional Test	-	-	4 (a)	Verify Truth Table without Load. V_{DD} = 3Vdc, V_{SS} = 0Vdc Notes 1 and 2	-	-	-
2	Functional Test	-	-	4 (a)	Verify Truth Table without Load. V_{DD} = 15Vdc, V_{SS} = 0Vdc Notes 1 and 2	-	-	-
3 to 18	Quiescent Current	I_{DD}	3005	4 (b)	V_{IL} = 0Vdc, V_{IH} = 15Vdc V_{DD} = 15Vdc, V_{SS} = 0Vdc Note 3 (Pin D/F 24) (Pin C 28)	-	500	nA
19 to 23	Input Current Low Level Address or Inhibit	I_{IL}	3009	4 (c)	V_{IN} (Under Test) = 0Vdc V_{IN} (Other Inputs) = 15Vdc V_{DD} = 15Vdc, V_{SS} = 0Vdc (Pins D/F 10-11-13-14-15) (Pins C 12-13-15-16-17)	-	-50	nA
24 to 28	Input Current High Level Address or Inhibit	I_{IH}	3010	4 (d)	V_{IN} (Under Test) = 15Vdc V_{IN} (Other Inputs) = 0Vdc V_{DD} = 15Vdc, V_{SS} = 0Vdc (Pins D/F 10-11-13-14-15) (Pins C 12-13-15-16-17)	-	50	nA

NOTES: See Page 25.

TABLE 3(b) - ELECTRICAL MEASUREMENTS AT LOW TEMPERATURE, -55(+5-0) °C (CONT'D)

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS MIN	LIMITS MAX	UNIT
29 to 44	Channel Off Leakage Current (Any Channel)	I_{OFF1}	-	4 (e)	V_{IN} (INHIBIT) = 15Vdc V_{IN} (Address Inputs) = 0Vdc V_{IN} (CHANNEL I/O) = 15Vdc V_{IN} (COMMON O/I) = 0Vdc V_{DD} = 15Vdc, V_{SS} = 0Vdc Pins D/F — Pins C 2 to 1 — 2 to 1 3 to 1 — 3 to 1 4 to 1 — 5 to 1 5 to 1 — 6 to 1 6 to 1 — 7 to 1 7 to 1 — 8 to 1 8 to 1 — 9 to 1 9 to 1 — 10 to 1 16 to 1 — 19 to 1 17 to 1 — 20 to 1 18 to 1 — 21 to 1 19 to 1 — 22 to 1 20 to 1 — 23 to 1 21 to 1 — 24 to 1 22 to 1 — 26 to 1 23 to 1 — 27 to 1	-	-100	nA
45 to 60	Channel Off Leakage Current (Any Channel)	I_{OFF2}	-	4 (e)	V_{IN} (INHIBIT) = 15Vdc V_{IN} (Address Inputs) = 0Vdc V_{IN} (CHANNEL I/O) = 0Vdc V_{IN} (COMMON I/O) = 15Vdc V_{DD} = 15Vdc, V_{SS} = 0Vdc Pins D/F — Pins C 1 to 2 — 1 to 2 1 to 3 — 1 to 3 1 to 4 — 1 to 5 1 to 5 — 1 to 6 1 to 6 — 1 to 7 1 to 7 — 1 to 8 1 to 8 — 1 to 9 1 to 9 — 1 to 10 1 to 16 — 1 to 19 1 to 17 — 1 to 20 1 to 18 — 1 to 21 1 to 19 — 1 to 22 1 to 20 — 1 to 23 1 to 21 — 1 to 24 1 to 22 — 1 to 26 1 to 23 — 1 to 27	-	100	nA

NOTES: See Page 25.

TABLE 3(b) - ELECTRICAL MEASUREMENTS AT LOW TEMPERATURE, -55(+5-0) °C (CONT'D)

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS MIN	LIMITS MAX	UNIT
61	Channel Off Leakage Current (All Channels)	I_{OFF3}	-	4 (f)	V_{IN} (INHIBIT) = 15Vdc V_{IN} (Address Inputs) = 0Vdc V_{IN} (ALL CHANNEL I/O) = 0Vdc V_{IN} (COMMON O/I) = 15Vdc V_{DD} = 15Vdc, V_{SS} = 0Vdc Pins D/F — Pins C 1 to 2 — 1 to 2 1 to 3 — 1 to 3 1 to 4 — 1 to 5 1 to 5 — 1 to 6 1 to 6 — 1 to 7 1 to 7 — 1 to 8 1 to 8 — 1 to 9 1 to 9 — 1 to 10 1 to 16 — 1 to 19 1 to 17 — 1 to 20 1 to 18 — 1 to 21 1 to 19 — 1 to 22 1 to 20 — 1 to 23 1 to 21 — 1 to 24 1 to 22 — 1 to 26 1 to 23 — 1 to 27	-	100	nA
62	Channel Off Leakage Current (All Channels)	I_{OFF4}	-	4 (f)	V_{IN} (INHIBIT) = 15Vdc V_{IN} (Address Inputs) = 0Vdc V_{IN} (ALL CHANNEL I/O) = 15Vdc V_{IN} (COMMON I/O) = 0Vdc V_{DD} = 15Vdc, V_{SS} = 0Vdc Pins D/F — Pins C 2 to 1 — 2 to 1 3 to 1 — 3 to 1 4 to 1 — 5 to 1 5 to 1 — 6 to 1 6 to 1 — 7 to 1 7 to 1 — 8 to 1 8 to 1 — 9 to 1 9 to 1 — 10 to 1 16 to 1 — 19 to 1 17 to 1 — 20 to 1 18 to 1 — 21 to 1 19 to 1 — 22 to 1 20 to 1 — 23 to 1 21 to 1 — 24 to 1 22 to 1 — 26 to 1 23 to 1 — 27 to 1	-	-100	nA

NOTES: See Page 25.

TABLE 3(b) - ELECTRICAL MEASUREMENTS AT LOW TEMPERATURE, – 55(+5–0) °C (CONT'D)

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS		UNIT
						MIN	MAX	
63 to 286	Channel On Resistance	R_{ON1}	-	4 (g)	V_{IN} (INHIBIT) = 0Vdc V_{IN} (Address Inputs): V_{IL} = 0Vdc, V_{IH} = 5Vdc I_{IN} = 100µAdc, R_L = 10kΩ Channel Input Conditions: See Test Table Figure 4(g)(i). V_{DD} = 5Vdc, V_{SS} = 0Vdc Note 4 Pins D/F — Pins C 1 to 2 — 1 to 2 1 to 3 — 1 to 3 1 to 4 — 1 to 5 1 to 5 — 1 to 6 1 to 6 — 1 to 7 1 to 7 — 1 to 8 1 to 8 — 1 to 9 1 to 9 — 1 to 10 1 to 16 — 1 to 19 1 to 17 — 1 to 20 1 to 18 — 1 to 21 1 to 19 — 1 to 22 1 to 20 — 1 to 23 1 to 21 — 1 to 24 1 to 22 — 1 to 26 1 to 23 — 1 to 27 2 to 1 — 2 to 1 3 to 1 — 3 to 1 4 to 1 — 5 to 1 5 to 1 — 6 to 1 6 to 1 — 7 to 1 7 to 1 — 8 to 1 8 to 1 — 9 to 1 9 to 1 — 10 to 1 16 to 1 — 19 to 1 17 to 1 — 20 to 1 18 to 1 — 21 to 1 19 to 1 — 22 to 1 20 to 1 — 23 to 1 21 to 1 — 24 to 1 22 to 1 — 26 to 1 23 to 1 — 27 to 1	-	800	Ω

NOTES: See Page 25.

TABLE 3(b) - ELECTRICAL MEASUREMENTS AT LOW TEMPERATURE, -55(+5-0) °C (CONT'D)

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS MIN	LIMITS MAX	UNIT
287 to 542	Channel On Resistance	R_{ON2}	-	4 (g)	V_{IN} (INHIBIT) = 0Vdc V_{IN} (Address Inputs): V_{IL} = 0Vdc, V_{IH} = 15Vdc I_{IN} = 100μAdc, R_L = 10kΩ Channel Input Conditions: See Test Table Figure 4(g)(i). V_{DD} = 15Vdc, V_{SS} = 0Vdc Note 4	-	200	Ω

Pins D/F	Pins C
1 to 2	1 to 2
1 to 3	1 to 3
1 to 4	1 to 5
1 to 5	1 to 6
1 to 6	1 to 7
1 to 7	1 to 8
1 to 8	1 to 9
1 to 9	1 to 10
1 to 16	1 to 19
1 to 17	1 to 20
1 to 18	1 to 21
1 to 19	1 to 22
1 to 20	1 to 23
1 to 21	1 to 24
1 to 22	1 to 26
1 to 23	1 to 27
2 to 1	2 to 1
3 to 1	3 to 1
4 to 1	5 to 1
5 to 1	6 to 1
6 to 1	7 to 1
7 to 1	8 to 1
8 to 1	9 to 1
9 to 1	10 to 1
16 to 1	19 to 1
17 to 1	20 to 1
18 to 1	21 to 1
19 to 1	22 to 1
20 to 1	23 to 1
21 to 1	24 to 1
22 to 1	26 to 1
23 to 1	27 to 1

NOTES: See Page 25.

TABLE 3(b) - ELECTRICAL MEASUREMENTS AT LOW TEMPERATURE, - 55(+5 - 0) °C (CONT'D)

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS		UNIT
						MIN	MAX	
543	Input Voltage Low Level (Noise Immunity) (Functional Test)	V_{IL1}	-	4 (h)	Address and Inhibit Inputs: V_{IL} = 1.5Vdc, V_{IH} = 3.5Vdc Channel Inputs: V_{IL} = 0Vdc, V_{IH} = 5Vdc V_{DD} = 5Vdc, V_{SS} = 0Vdc Note 5 (Pins D/F 2-3-4-5-6-7-8-9-16-17-18-19-20-21-22-23) (Pins C 2-3-5-6-7-8-9-10-19-21-22-23-24-26-27)	-	0.5	V
	Input Voltage High Level (Noise Immunity) (Functional Test)	V_{IH1}				4.5	-	
544	Input Voltage Low Level (Noise Immunity) (Functional Test)	V_{IL2}	-	4 (h)	Address and Inhibit Inputs: V_{IL} = 4Vdc, V_{IH} = 11Vdc Channel Inputs: V_{IL} = 0Vdc, V_{IH} = 15Vdc V_{DD} = 15Vdc, V_{SS} = 0Vdc Note 5 (Pins D/F 2-3-4-5-6-7-8-9-16-17-18-19-20-21-22-23) (Pins C 2-3-5-6-7-8-9-10-19-21-22-23-24-26-27)	-	1.5	V
	Input Voltage High Level (Noise Immunity) (Functional Test)	V_{IH2}				13.5	-	
545	Threshold Voltage N-Channel	V_{THN}	-	4 (i)	Inhibit Input at Ground. All Other Inputs: V_{IN} = 5Vdc V_{DD} = 5Vdc, I_{SS} = -10µA (Pin D/F 12) (Pin C 14)	-0.7	-3.5	V
546	Threshold Voltage P-Channel	V_{THP}	-	4 (j)	Inhibit Input at Ground. All Other Inputs: V_{IN} = -5Vdc V_{SS} = -5Vdc, I_{DD} = 10µA (Pin D/F 24) (Pin C 28)	0.7	3.5	V

NOTES: See Page 25.

FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS

FIGURE 4 (a) - FUNCTIONAL TEST TABLE

PATTERN NO.	PIN NUMBERS																					D.C. SUPPLY	
	1	2	3	4	5	6	7	8	9	10	11	13	14	15	16	17	18	19	20	21	22	23	12	24
1	1	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	V_{DD}
2	1	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	0	0	0	0		
3	1	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0		
4	1	0	0	0	0	0	1	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0		
5	1	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0		
6	1	0	0	0	1	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0		
7	1	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0		
8	1	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	1		
9	1	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0		
10	1	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0		
11	1	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0		
12	1	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	0	0	0	0		
13	1	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0		
14	1	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	0	0	0	0		
15	1	0	0	0	0	1	0	0	0	1	1	0	0	0	0	0	0	0	0	0	0	0		
16	1	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	0	0	0	0		
17	1	0	0	1	0	0	0	0	0	1	0	0	1	0	0	0	0	0	0	0	0	0		
18	1	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	0	0	0	0		
19	1	0	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	1	0		
20	1	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	0	0	0	0		
21	1	0	0	0	0	0	0	0	0	1	0	0	0	1	0	0	0	0	0	0	0	0		
22	1	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	0	0	0	0		
23	1	0	0	0	0	0	1	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0		
24	1	0	0	0	0	1	0	0	0	1	1	0	0	0	0	0	0	0	0	0	0	0		
25	1	0	0	0	0	0	1	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0		
26	1	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0		
27	1	0	0	0	0	0	1	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0		
28	1	0	1	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	0		
29	1	0	0	0	0	0	1	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0		
30	1	0	0	0	0	0	0	0	0	0	1	1	0	0	0	0	0	0	0	1	0	0		
31	1	0	0	0	0	0	1	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0		
32	1	0	0	0	0	0	0	0	0	0	1	0	0	1	0	0	0	0	0	0	0	0		
33	1	0	0	0	0	0	1	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0		
34	1	0	0	0	0	1	0	0	0	1	1	0	0	0	0	0	0	0	0	0	0	0		
35	1	0	0	0	0	0	1	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0		
36	1	0	0	0	0	1	0	0	0	1	1	0	0	0	0	0	0	0	0	0	0	0		
37	1	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	0	0	0	0		
38	1	0	0	0	0	1	0	0	0	1	1	0	0	0	0	0	0	0	0	0	0	0		
39	1	1	0	0	0	0	0	0	0	1	1	0	1	0	0	0	0	0	0	0	0	0		
40	1	0	0	0	0	1	0	0	0	1	1	0	0	0	0	0	0	0	0	0	0	0		
41	1	0	0	0	0	0	0	0	0	1	1	1	0	0	0	0	0	0	1	0	0	0		
42	1	0	0	0	0	1	0	0	0	1	1	0	0	0	0	0	0	0	0	0	0	0		
43	1	0	0	0	0	0	0	0	0	1	1	0	0	1	0	0	0	0	0	0	0	0		
44	1	0	0	0	0	1	0	0	0	1	1	0	0	0	0	0	0	0	0	0	0	0		

NOTES: See Page 42.

FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS (CONTINUED)

FIGURE 4 (a) - FUNCTIONAL TEST TABLE (CONT'D)

PATTERN NO.	PIN NUMBERS																					D.C. SUPPLY	
	1	2	3	4	5	6	7	8	9	10	11	13	14	15	16	17	18	19	20	21	22	23	12	24
45	1	0	0	0	1	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	V_{DD}
46	1	0	0	1	0	0	0	0	0	1	0	0	1	0	0	0	0	0	0	0	0	0		
47	1	0	0	0	1	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0		
48	1	0	1	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	0		
49	1	0	0	0	1	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0		
50	1	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0		
51	1	0	0	0	1	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0		
52	1	0	0	0	0	0	0	0	0	0	0	1	1	0	0	0	0	0	1	0	0	0		
53	1	0	0	0	1	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0		
54	1	0	0	0	0	0	0	0	0	0	0	0	1	1	0	0	0	0	0	0	0	0		
55	1	0	0	0	1	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0		
56	1	0	0	1	0	0	0	0	0	1	0	0	1	0	0	0	0	0	0	0	0	0		
57	1	0	0	0	1	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0		
58	1	0	0	1	0	0	0	0	0	1	0	0	1	0	0	0	0	0	0	0	0	0		
59	1	1	0	0	0	0	0	0	0	1	1	0	1	0	0	0	0	0	0	0	0	0		
60	1	0	0	1	0	0	0	0	0	1	0	0	1	0	0	0	0	0	0	0	0	0		
61	1	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	0	0	0	0		
62	1	0	0	1	0	0	0	0	0	1	0	0	1	0	0	0	0	0	0	0	0	0		
63	1	0	0	0	0	0	0	0	0	1	0	1	1	0	0	0	1	0	0	0	0	0		
64	1	0	0	1	0	0	0	0	0	1	0	0	1	0	0	0	0	0	0	0	0	0		
65	1	0	0	0	0	0	0	0	0	1	0	0	1	1	0	0	0	0	0	0	0	0		
66	1	0	0	1	0	0	0	0	0	1	0	0	1	0	0	0	0	0	0	0	0	0		
67	1	0	1	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	0		
68	1	1	0	0	0	0	0	0	0	1	1	0	1	0	0	0	0	0	0	0	0	0		
69	1	0	1	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	0		
70	1	0	0	0	1	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0		
71	1	0	1	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	0		
72	1	0	0	0	0	0	1	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0		
73	1	0	1	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	0		
74	1	0	0	0	0	0	0	0	0	0	1	1	1	0	0	1	0	0	0	0	0	0		
75	1	0	1	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	0		
76	1	0	0	0	0	0	0	0	0	0	1	0	1	1	0	0	0	0	0	0	0	0		
77	1	0	1	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	0		
78	1	1	0	0	0	0	0	0	0	1	1	0	1	0	0	0	0	0	0	0	0	0		
79	1	0	1	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	0		
80	1	1	0	0	0	0	0	0	0	1	1	0	1	0	0	0	0	0	0	0	0	0		
81	1	0	0	1	0	0	0	0	0	1	0	0	1	0	0	0	0	0	0	0	0	0		
82	1	1	0	0	0	0	0	0	0	1	1	0	1	0	0	0	0	0	0	0	0	0		
83	1	0	0	0	0	1	0	0	0	1	1	0	0	0	0	0	0	0	0	0	0	0		
84	1	1	0	0	0	0	0	0	0	1	1	0	1	0	0	0	0	0	0	0	0	0		
85	1	0	0	0	0	0	0	0	0	1	1	1	1	0	1	0	0	0	0	0	0	0		
86	1	1	0	0	0	0	0	0	0	1	1	0	1	0	0	0	0	0	0	0	0	0		
87	1	0	0	0	0	0	0	0	0	1	1	0	1	1	0	0	0	0	0	0	0	0		
88	1	1	0	0	0	0	0	0	0	1	1	0	1	0	0	0	0	0	0	0	0	0		

NOTES: See Page 42.

FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS (CONTINUED)

FIGURE 4 (a) - FUNCTIONAL TEST TABLE (CONT'D)

PATTERN NO.	PIN NUMBERS																						D.C. SUPPLY	
	1	2	3	4	5	6	7	8	9	10	11	13	14	15	16	17	18	19	20	21	22	23	12	24
89	1	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	1	0	V_{DD}
90	1	0	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	1	0		
91	1	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	1		
92	1	0	0	0	0	0	0	0	0	0	1	1	0	0	0	0	0	0	0	1	0	0		
93	1	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	1		
94	1	0	0	0	0	0	0	0	0	0	0	1	1	0	0	0	0	1	0	0	0	0		
95	1	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0		
96	1	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0		
97	1	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	1		
98	1	0	0	0	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0		
99	1	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	1		
100	1	0	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	1	0		
101	1	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	1		
102	1	0	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	1	0		
103	1	0	0	0	0	0	0	0	0	1	1	1	0	0	0	0	0	0	1	0	0	0		
104	1	0	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	1	0		
105	1	0	0	0	0	0	0	0	0	1	0	1	1	0	0	0	1	0	0	0	0	0		
106	1	0	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	1	0		
107	1	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	0	0	0	0		
108	1	0	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	1	0		
109	1	0	0	0	0	0	0	0	0	1	0	1	0	1	0	0	0	0	0	0	0	0		
110	1	0	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	1	0		
111	1	0	0	0	0	0	0	0	0	0	1	1	0	0	0	0	0	0	0	1	0	0		
112	1	0	0	0	0	0	0	0	0	1	1	1	0	0	0	0	0	0	1	0	0	0		
113	1	0	0	0	0	0	0	0	0	0	1	1	0	0	0	0	0	0	0	1	0	0		
114	1	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	1		
115	1	0	0	0	0	0	0	0	0	0	1	1	0	0	0	0	0	0	0	1	0	0		
116	1	0	0	0	0	0	0	0	0	0	1	1	1	0	0	1	0	0	0	0	0	0		
117	1	0	0	0	0	0	0	0	0	0	1	1	0	0	0	0	0	0	0	1	0	0		
118	1	0	0	0	0	0	1	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0		
119	1	0	0	0	0	0	0	0	0	0	1	1	0	0	0	0	0	0	0	1	0	0		
120	1	0	0	0	0	0	0	0	0	0	1	1	0	1	0	0	0	0	0	0	0	0		
121	1	0	0	0	0	0	0	0	0	0	1	1	0	0	0	0	0	0	0	1	0	0		
122	1	0	0	0	0	0	0	0	0	1	1	1	0	0	0	0	0	0	1	0	0	0		
123	1	0	0	0	0	0	0	0	0	0	1	1	0	0	0	0	0	0	0	1	0	0		
124	1	0	0	0	0	0	0	0	0	1	1	1	0	0	0	0	0	0	1	0	0	0		
125	1	0	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	1	0		
126	1	0	0	0	0	0	0	0	0	1	1	1	0	0	0	0	0	0	1	0	0	0		
127	1	0	0	0	0	0	0	0	0	1	1	1	1	0	1	0	0	0	0	0	0	0		
128	1	0	0	0	0	0	0	0	0	1	1	1	0	0	0	0	0	0	1	0	0	0		
129	1	0	0	0	0	1	0	0	0	1	1	0	0	0	0	0	0	0	0	0	0	0		
130	1	0	0	0	0	0	0	0	0	1	1	1	0	0	0	0	0	0	1	0	0	0		
131	1	0	0	0	0	0	0	0	0	1	1	1	0	1	0	0	0	0	0	0	0	0		
132	1	0	0	0	0	0	0	0	0	1	1	1	0	0	0	0	0	0	1	0	0	0		

NOTES: See Page 42.

FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS (CONTINUED)

FIGURE 4 (a) - FUNCTIONAL TEST TABLE (CONT'D)

PATTERN NO.	PIN NUMBERS																						D.C. SUPPLY	
	1	2	3	4	5	6	7	8	9	10	11	13	14	15	16	17	18	19	20	21	22	23	12	24
133	1	0	0	0	0	0	0	0	0	0	0	1	1	0	0	0	0	1	0	0	0	0	0	V_{DD}
134	1	0	0	0	0	0	0	0	0	1	0	1	1	0	0	0	1	0	0	0	0	0		
135	1	0	0	0	0	0	0	0	0	0	0	1	1	0	0	0	0	1	0	0	0	0		
136	1	0	0	0	0	0	0	0	0	0	1	1	1	0	0	1	0	0	0	0	0	0		
137	1	0	0	0	0	0	0	0	0	0	0	1	1	0	0	0	0	1	0	0	0	0		
138	1	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	1		
139	1	0	0	0	0	0	0	0	0	0	0	1	1	0	0	0	0	1	0	0	0	0		
140	1	0	0	0	1	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0		
141	1	0	0	0	0	0	0	0	0	0	0	1	1	0	0	0	0	1	0	0	0	0		
142	1	0	0	0	0	0	0	0	0	0	0	1	1	1	0	0	0	0	0	0	0	0		
143	1	0	0	0	0	0	0	0	0	0	0	1	1	0	0	0	0	1	0	0	0	0		
144	1	0	0	0	0	0	0	0	0	1	0	1	1	0	0	0	1	0	0	0	0	0		
145	1	0	0	0	0	0	0	0	0	0	0	1	1	0	0	0	0	1	0	0	0	0		
146	1	0	0	0	0	0	0	0	0	1	0	1	1	0	0	0	1	0	0	0	0	0		
147	1	0	0	0	0	0	0	0	0	1	1	1	1	0	1	0	0	0	0	0	0	0		
148	1	0	0	0	0	0	0	0	0	1	0	1	1	0	0	0	1	0	0	0	0	0		
149	1	0	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	1	0		
150	1	0	0	0	0	0	0	0	0	1	0	1	1	0	0	0	1	0	0	0	0	0		
151	1	0	0	1	0	0	0	0	0	1	0	0	1	0	0	0	0	0	0	0	0	0		
152	1	0	0	0	0	0	0	0	0	1	0	1	1	0	0	0	1	0	0	0	0	0		
153	1	0	0	0	0	0	0	0	0	1	0	1	1	1	0	0	0	0	0	0	0	0		
154	1	0	0	0	0	0	0	0	0	1	0	1	1	0	0	0	1	0	0	0	0	0		
155	1	0	0	0	0	0	0	0	0	0	1	1	1	0	0	1	0	0	0	0	0	0		
156	1	0	0	0	0	0	0	0	0	1	1	1	1	0	1	0	0	0	0	0	0	0		
157	1	0	0	0	0	0	0	0	0	0	1	1	1	0	0	1	0	0	0	0	0	0		
158	1	0	0	0	0	0	0	0	0	0	0	1	1	0	0	0	0	1	0	0	0	0		
159	1	0	0	0	0	0	0	0	0	0	1	1	1	0	0	1	0	0	0	0	0	0		
160	1	0	0	0	0	0	0	0	0	0	1	1	0	0	0	0	0	0	0	1	0	0		
161	1	0	0	0	0	0	0	0	0	0	1	1	1	0	0	1	0	0	0	0	0	0		
162	1	0	1	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	0		
163	1	0	0	0	0	0	0	0	0	0	1	1	1	0	0	1	0	0	0	0	0	0		
164	1	0	0	0	0	0	0	0	0	0	1	1	1	1	0	0	0	0	0	0	0	0		
165	1	0	0	0	0	0	0	0	0	0	1	1	1	0	0	1	0	0	0	0	0	0		
166	1	0	0	0	0	0	0	0	0	1	1	1	1	0	1	0	0	0	0	0	0	0		
167	1	0	0	0	0	0	0	0	0	0	1	1	1	0	0	1	0	0	0	0	0	0		
168	1	0	0	0	0	0	0	0	0	1	1	1	1	0	1	0	0	0	0	0	0	0		
169	1	0	0	0	0	0	0	0	0	1	0	1	1	0	0	0	1	0	0	0	0	0		
170	1	0	0	0	0	0	0	0	0	1	1	1	1	0	1	0	0	0	0	0	0	0		
171	1	0	0	0	0	0	0	0	0	1	1	1	0	0	0	0	0	0	1	0	0	0		
172	1	0	0	0	0	0	0	0	0	1	1	1	1	0	1	0	0	0	0	0	0	0		
173	1	1	0	0	0	0	0	0	0	1	1	0	1	0	0	0	0	0	0	0	0	0		
174	1	0	0	0	0	0	0	0	0	1	1	1	1	0	1	0	0	0	0	0	0	0		
175	1	0	0	0	0	0	0	0	0	1	1	1	1	1	0	0	0	0	0	0	0	0		
176	1	0	0	0	0	0	0	0	0	1	1	1	1	0	1	0	0	0	0	0	0	0		

NOTES: See Page 42.

FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS (CONTINUED)

FIGURE 4 (a) - FUNCTIONAL TEST TABLE (CONT'D)

NOTES

1. Figure 4 (a) illustrates one series of Test Patterns. Any other test pattern series must be agreed with the Qualifying Space Agency and shall be included as an Appendix.

2. Test Set-up:
   - Common Switch Output connected to V_{DD} supply.
   - Switch Inputs connected individually through 33kΩ to V_{SS} supply and to the digital comparator and through 100kΩ at V_{DD} = 3Vdc.

3. Logic Level Definitions: 1 = V_{IH} = V_{DD}, 0 = V_{IL} = V_{SS}.

FIGURE 4 (b) - QUIESCENT CURRENT TEST TABLE

PATTERN NO.	PIN NUMBERS																					D.C. SUPPLY	
	1	2	3	4	5	6	7	8	9	10	11	13	14	15	16	17	18	19	20	21	22	23	12	24
1	1	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	V_{DD}
2	1	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	0	0	0	0	↓	↓
3	1	0	0	0	0	0	1	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	↓	↓
4	1	0	0	0	0	1	0	0	0	1	1	0	0	0	0	0	0	0	0	0	0	0	↓	↓
5	1	0	0	0	1	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	↓	↓
6	1	0	0	1	0	0	0	0	0	1	0	0	1	0	0	0	0	0	0	0	0	0	↓	↓
7	1	0	1	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	0	↓	↓
8	1	1	0	0	0	0	0	0	0	1	1	0	1	0	0	0	0	0	0	0	0	0	↓	↓
9	1	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	1	↓	↓
10	1	0	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	0	1	0	↓	↓
11	1	0	0	0	0	0	0	0	0	0	1	1	0	0	0	0	0	0	0	1	0	0	↓	↓
12	1	0	0	0	0	0	0	0	0	1	1	1	0	0	0	0	0	0	1	0	0	0	↓	↓
13	1	0	0	0	0	0	0	0	0	0	0	1	1	0	0	0	0	1	0	0	0	0	↓	↓
14	1	0	0	0	0	0	0	0	0	1	0	1	1	0	0	0	1	0	0	0	0	0	↓	↓
15	1	0	0	0	0	0	0	0	0	0	1	1	1	0	0	1	0	0	0	0	0	0	↓	↓
16	1	0	0	0	0	0	0	0	0	1	1	1	1	0	1	0	0	0	0	0	0	0	↓	↓
VR	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	↓	↓

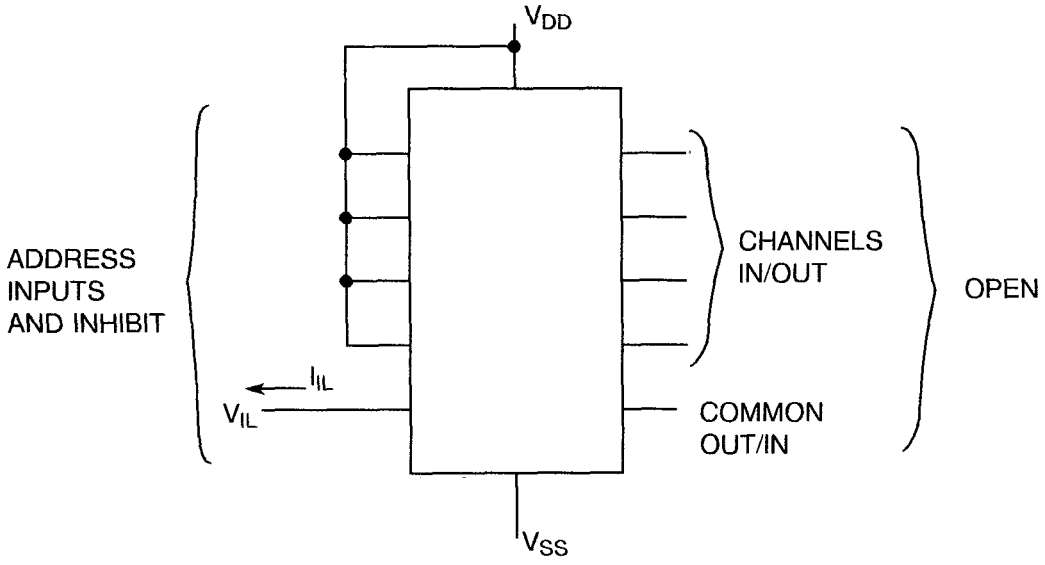
NOTES

1. Figure 4 (b) illustrates one series of Test Patterns. Any other pattern series must be agreed with the Qualifying Space Agency and shall be included as an Appendix.

2. Logic Level Definitions: 1 = V_{IH} = V_{DD}, 0 = V_{IL} = V_{SS}.

FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS (CONTINUED)

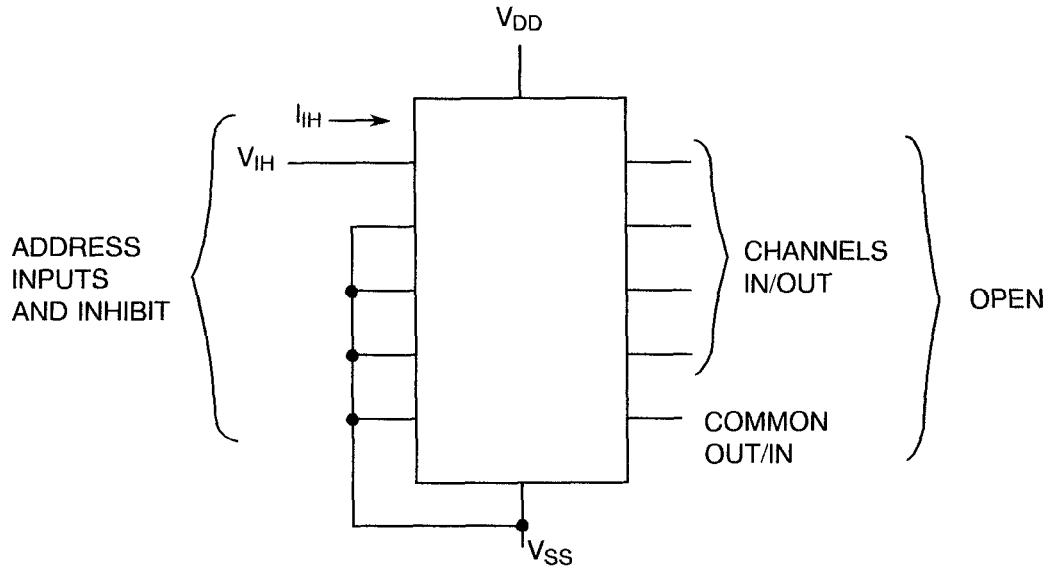
FIGURE 4(c) - INPUT CURRENT LOW LEVEL



NOTES

1. Each input to be tested separately.

FIGURE 4(d) - INPUT CURRENT HIGH LEVEL

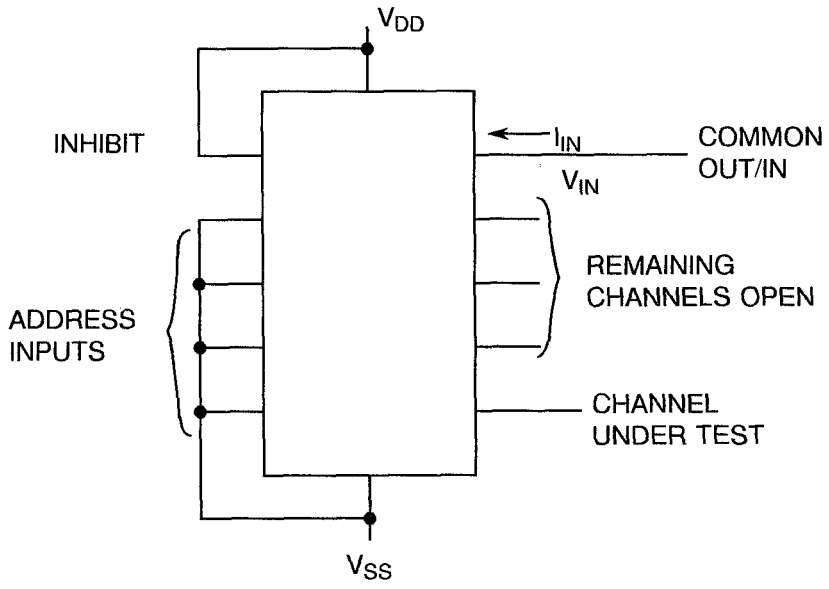


NOTES

1. Each input to be tested separately.

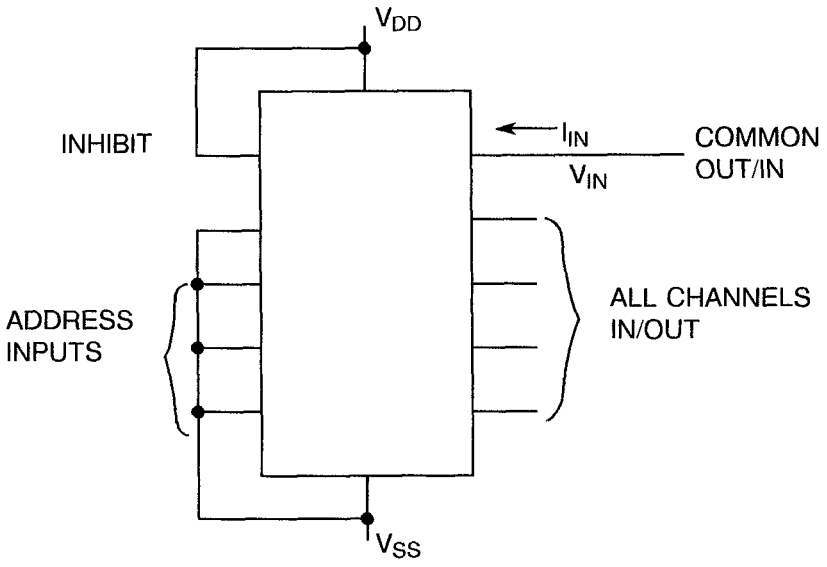
FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS (CONTINUED)

FIGURE 4(e) - CHANNEL OFF LEAKAGE CURRENT



NOTES
1. Each output to be tested separately.

FIGURE 4(f) - CHANNEL TOTAL OFF LEAKAGE CURRENT



NOTES
1. Each output to be tested separately.

FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS (CONTINUED)

FIGURE 4 (g)(i) - TEST TABLE FOR CHANNEL ON RESISTANCE

TEST NO.	INH.	ADDRESS				INPUT CONDITIONS (PIN NUMBERS) CHANNEL NUMBERS																Z	NOTES 1, 2 & 3
		A	B	C	D	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15		
1	0	0	0	0	0																	V_{IS}	
2		1	0	0	0		0																
3		0	1	0	0			0															
4		1	1	0	0				0														
5		0	0	1	0					0													
6		1	0	1	0						0												
7		0	1	1	0							0											
8		1	1	1	0								0										
9		0	0	0	1									0									
10		1	0	0	1										0								
11		0	1	0	1											0							
12		1	1	0	1												0						
13		0	0	1	1													0					
14		1	0	1	1														0				
15		0	1	1	1															0			
16		1	1	1	1																0		
17		0	0	0	0	V_{IS}																0	
18		1	0	0	0		V_{IS}																
19		0	1	0	0			V_{IS}															
20		1	1	0	0				V_{IS}														
21		0	0	1	0					V_{IS}													
22		1	0	1	0						V_{IS}												
23		0	1	1	0							V_{IS}											
24		1	1	1	0								V_{IS}										
25		0	0	0	1									V_{IS}									
26		1	0	0	1										V_{IS}								
27		0	1	0	1											V_{IS}							
28		1	1	0	0												V_{IS}						
29		0	0	1	1													V_{IS}					
30		1	0	1	1														V_{IS}				
31		0	1	1	1															V_{IS}			
32		1	1	1	1																V_{IS}		

NOTES: See Page 46.

FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS (CONTINUED)

FIGURE 4 (g)(i) - TEST TABLE FOR CHANNEL ON RESISTANCE (CONTINUED)

NOTES

1. Logic Level Definitions: 1 = V_{IH} = V_{DD}, 0 = V_{IL} = V_{SS}.

2. For V_{IS} the following notes apply:-

   (i) V_{IN} (FORCED) 0—— T.G. ——0 V_{OUT} (MEASURED LIMIT)

   (ii) R_{ON} 5V: V_{IN} = 1.5V, 1.9V, 2.3V, 2.7V, 3.3V, 3.7V, 4.1V,
   V_{OUT} = V_{IN} - 200mV

   (iii) R_{ON} 15V: V_{IN} = 1.5V, 1.9V, 2.3V, 2.7V, 13.3V, 13.7V, 14.1V, 14.5V,
   V_{OUT} = V_{IN} - 200mV

FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS (CONTINUED)

FIGURE 4(g)(ii) - CHANNEL ON RESISTANCE

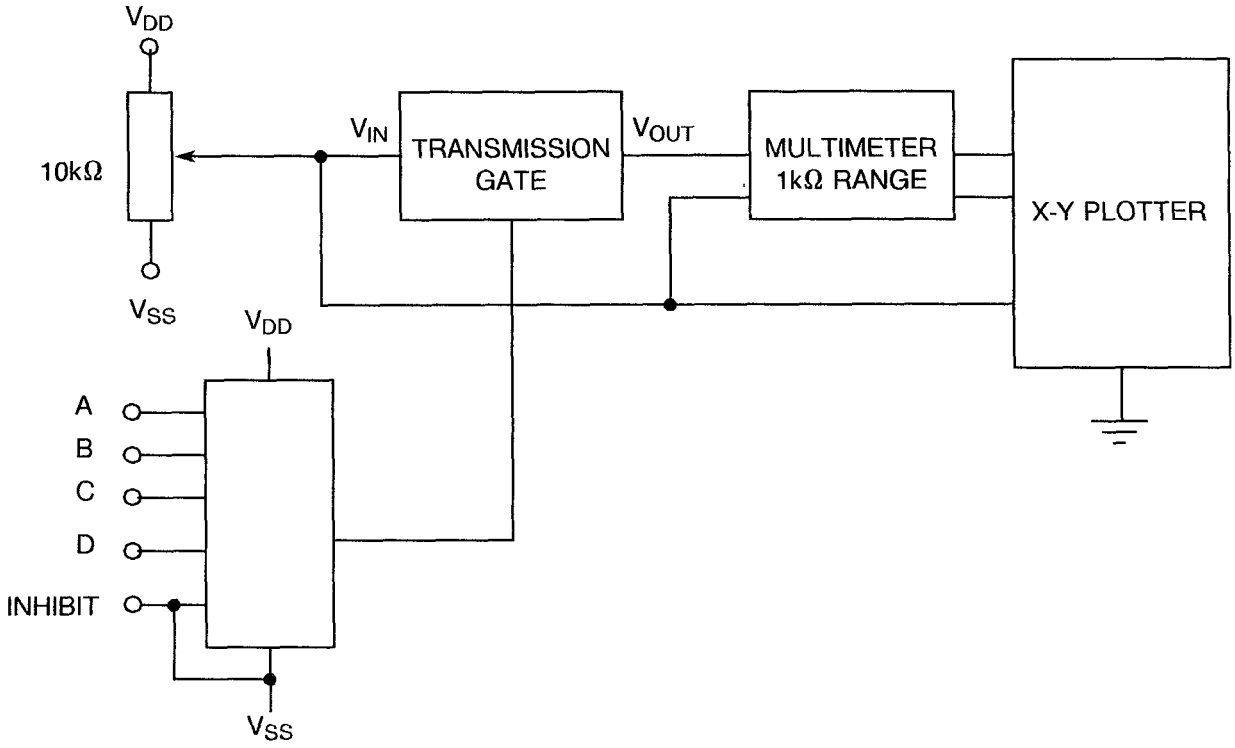


FIGURE 4(g)(iii) - CHANNEL ON RESISTANCE

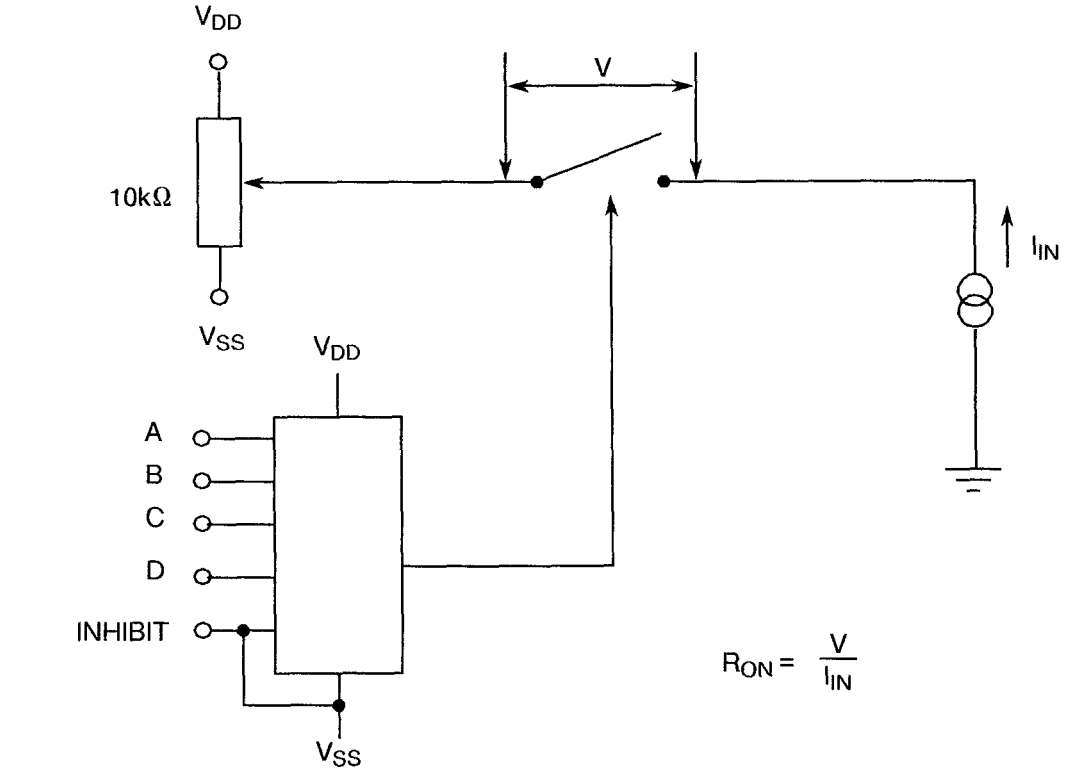
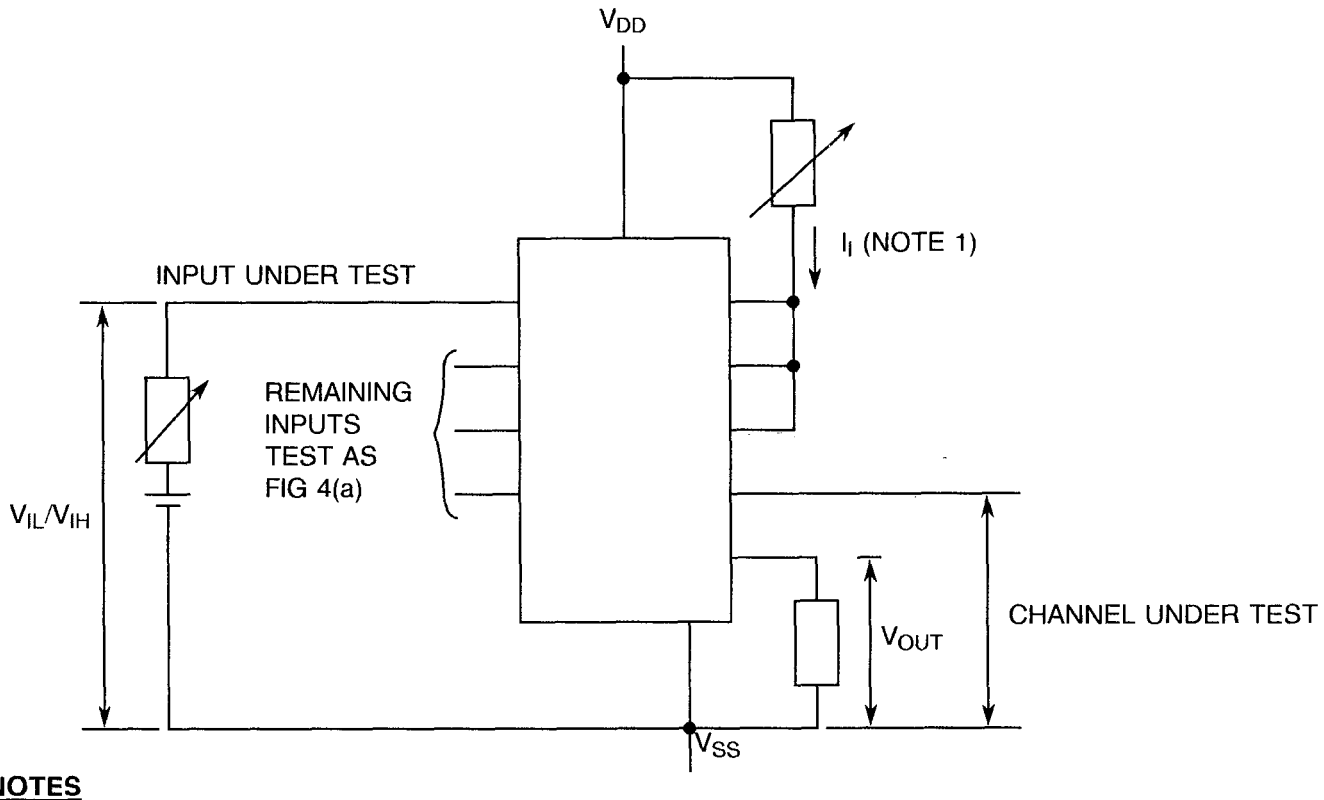


FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS (CONTINUED)

FIGURE 4(h) - INPUT VOLTAGE HIGH AND LOW LEVEL



NOTES

1. I_I < 2µA for all OFF Channels.

FIGURE 4(i) - THRESHOLD VOLTAGE N-CHANNEL

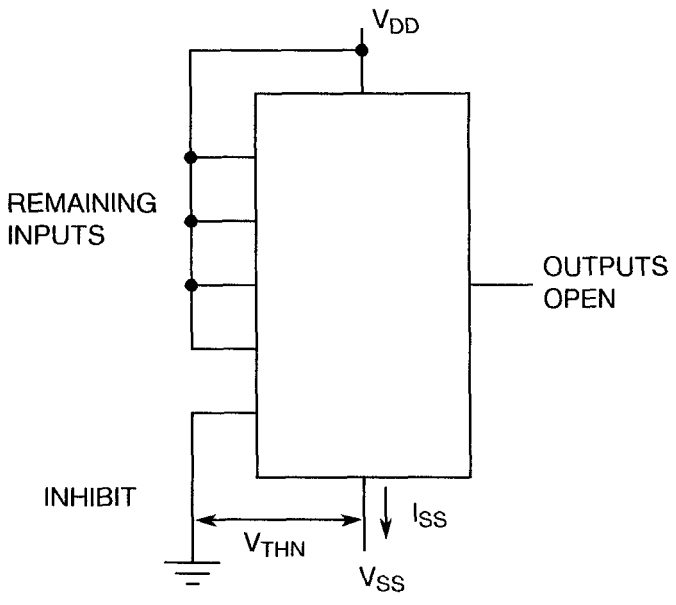


FIGURE 4(i) - THRESHOLD VOLTAGE P-CHANNEL

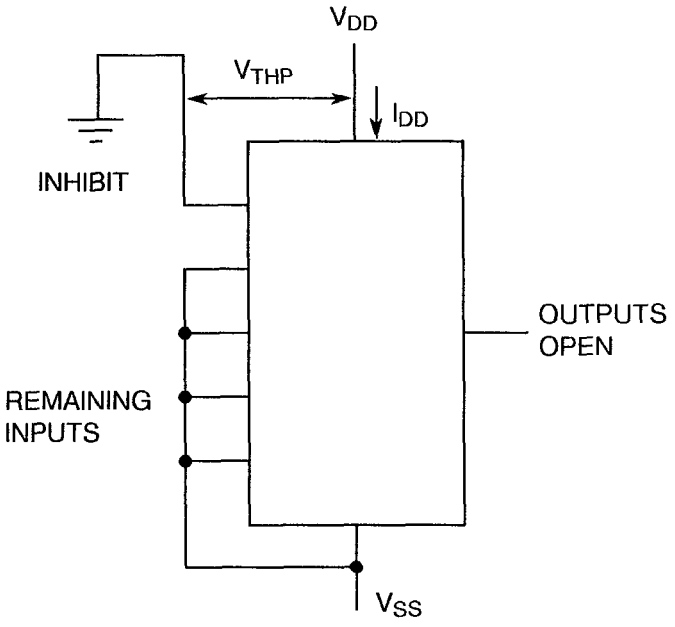
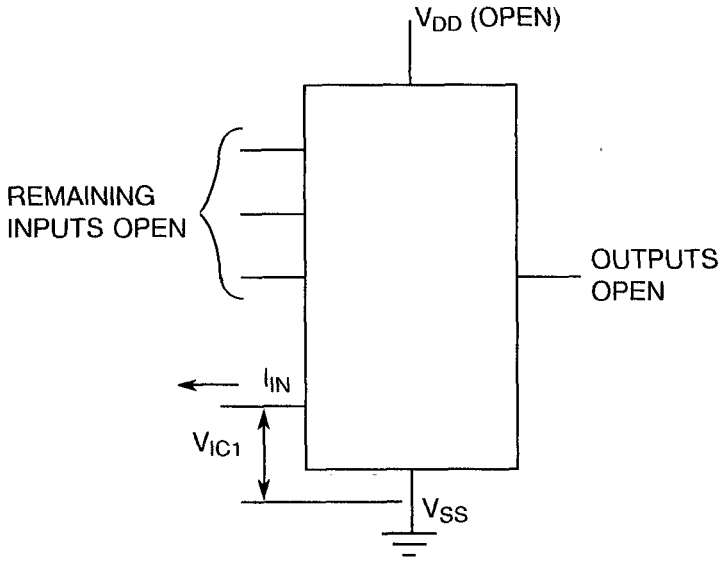


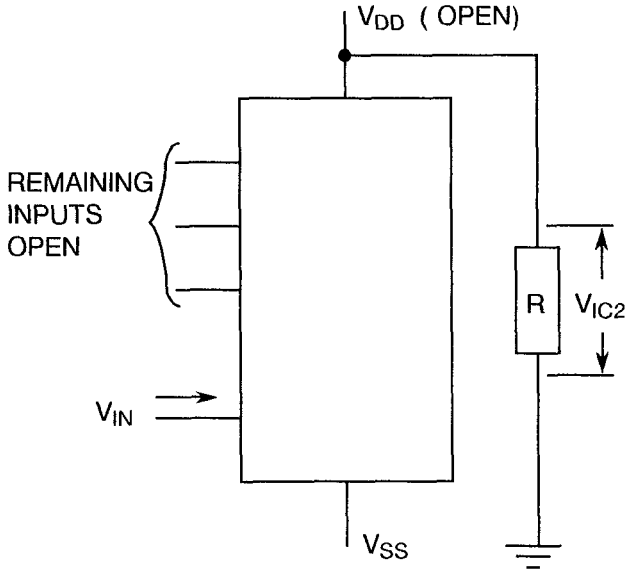
FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS (CONTINUED)

FIGURE 4(k) - INPUT CLAMP VOLTAGE (V_{SS})



NOTES
1. Each input to be tested separately.

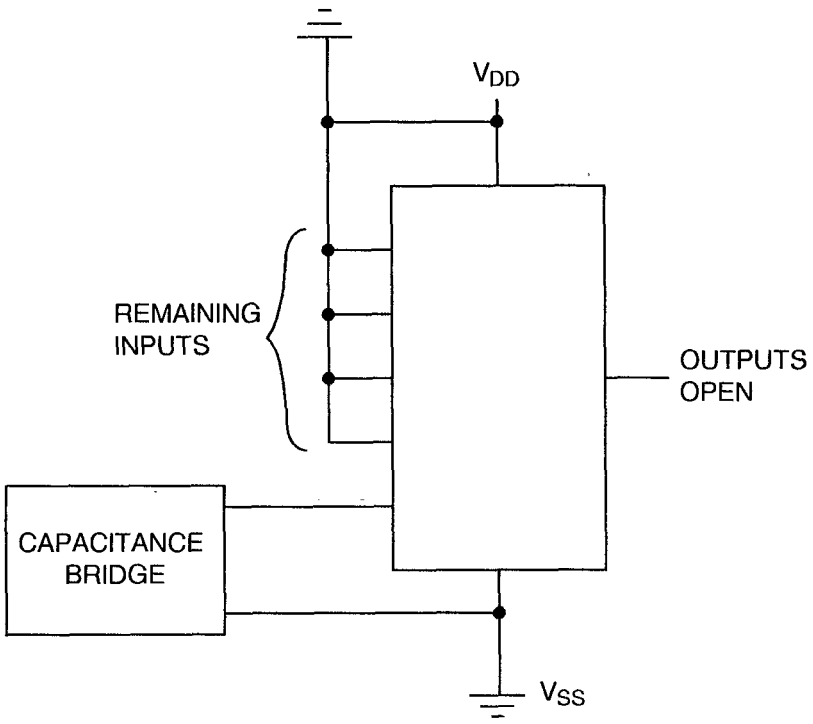
FIGURE 4(l) - INPUT CLAMP VOLTAGE (V_{DD})



NOTES
1. Each input to be tested separately.

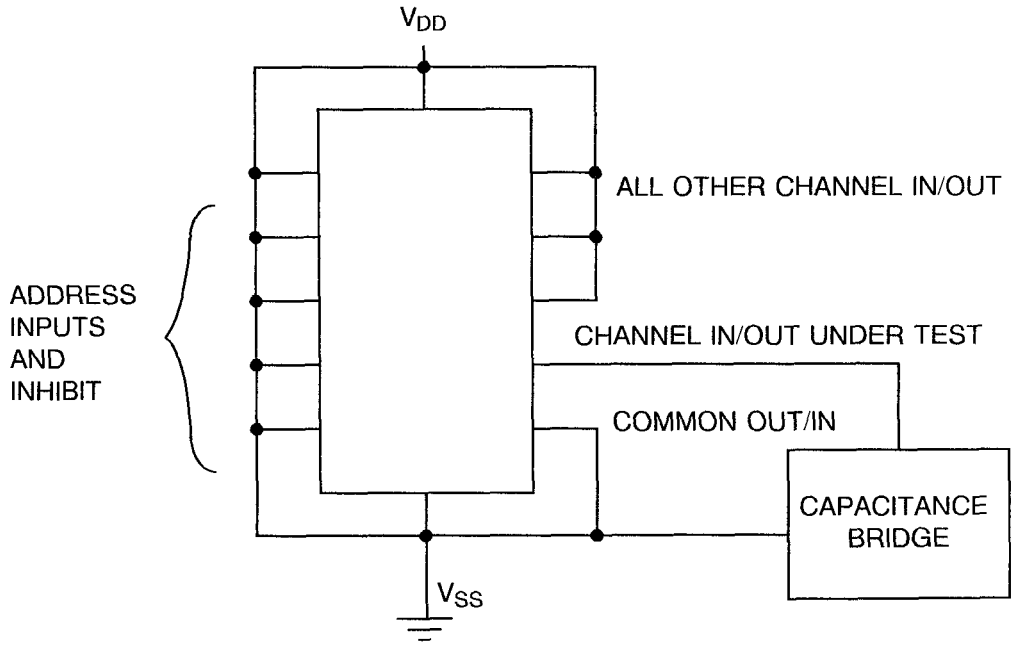
FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS (CONTINUED)

FIGURE 4(m) - INPUT CAPACITANCE, ADDRESS AND INHIBIT



NOTES
1. Each input to be tested separately.
2. f = 100kHz to 1MHz.

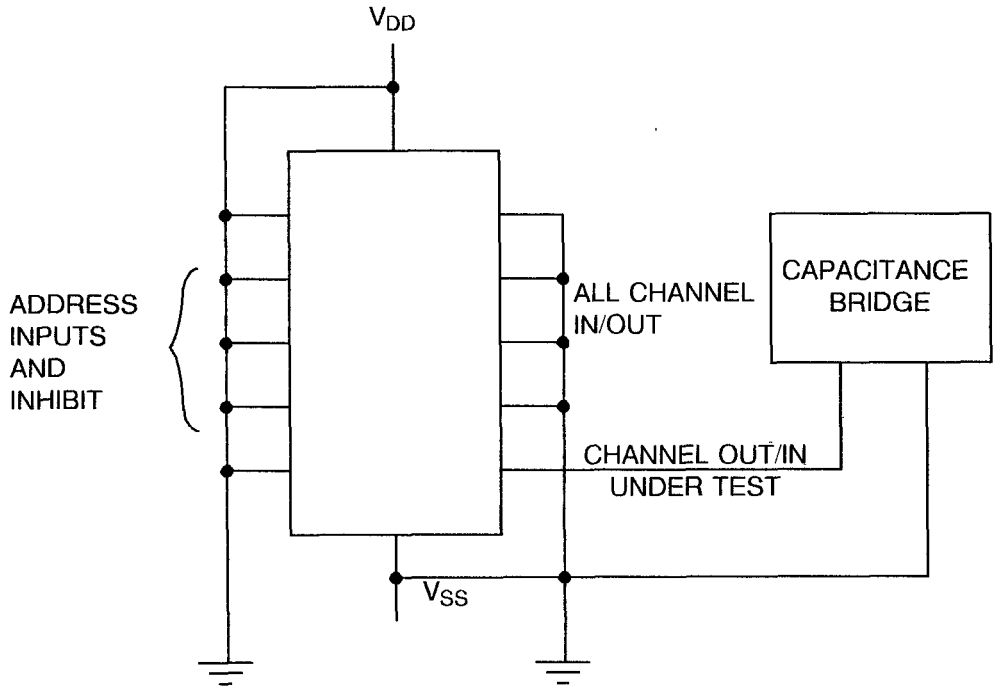
FIGURE 4(n) - CHANNEL INPUT CAPACITANCE



NOTES
1. Each input to be tested separately.
2. f = 100kHz to 1MHz.

FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS (CONTINUED)

FIGURE 4(o) - CHANNEL OUTPUT CAPACITANCE

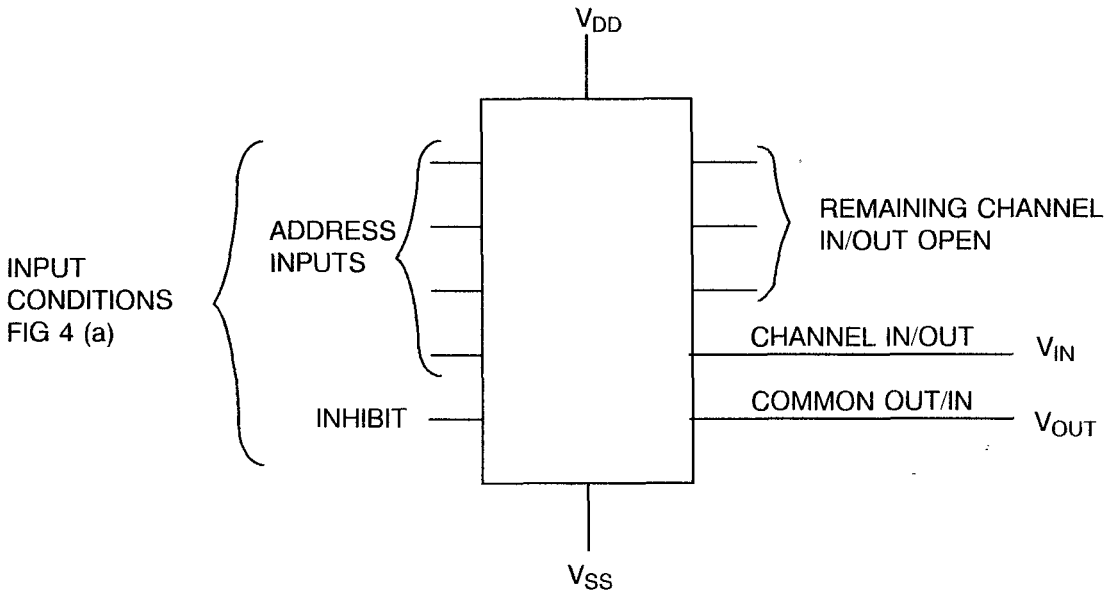


NOTES

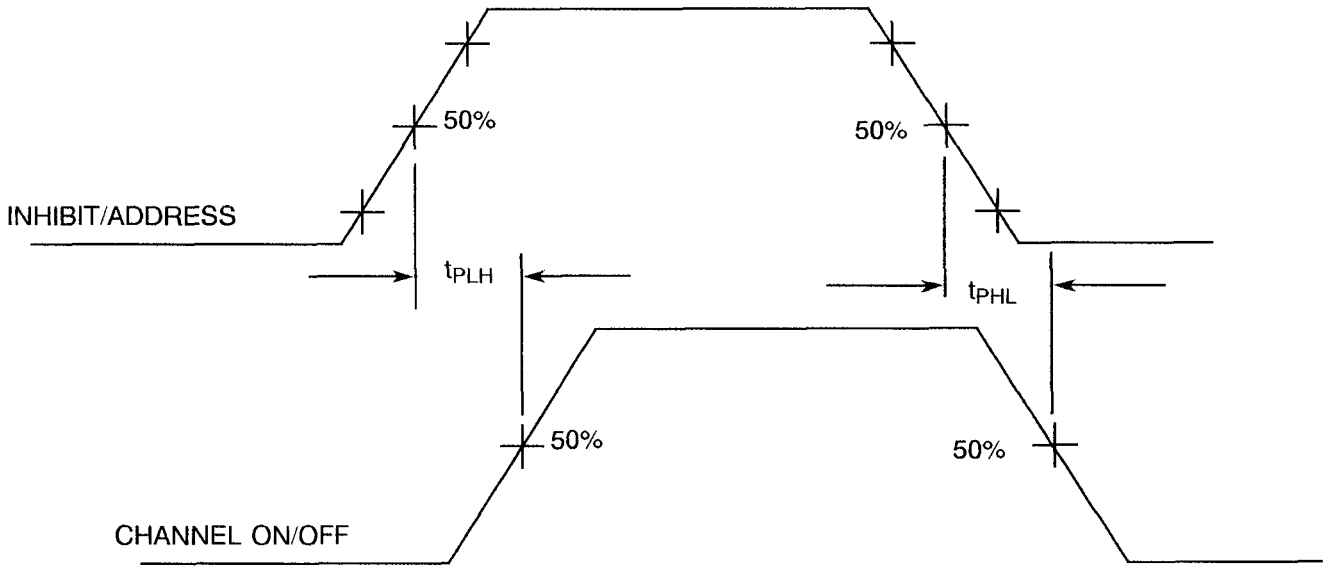
1. Each output to be tested separately.
2. f = 100kHz to 1MHz.

FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS (CONTINUED)

FIGURE 4 (p) - PROPAGATION DELAY, INHIBIT OR ADDRESS INPUTS TO CHANNEL ON OR OFF



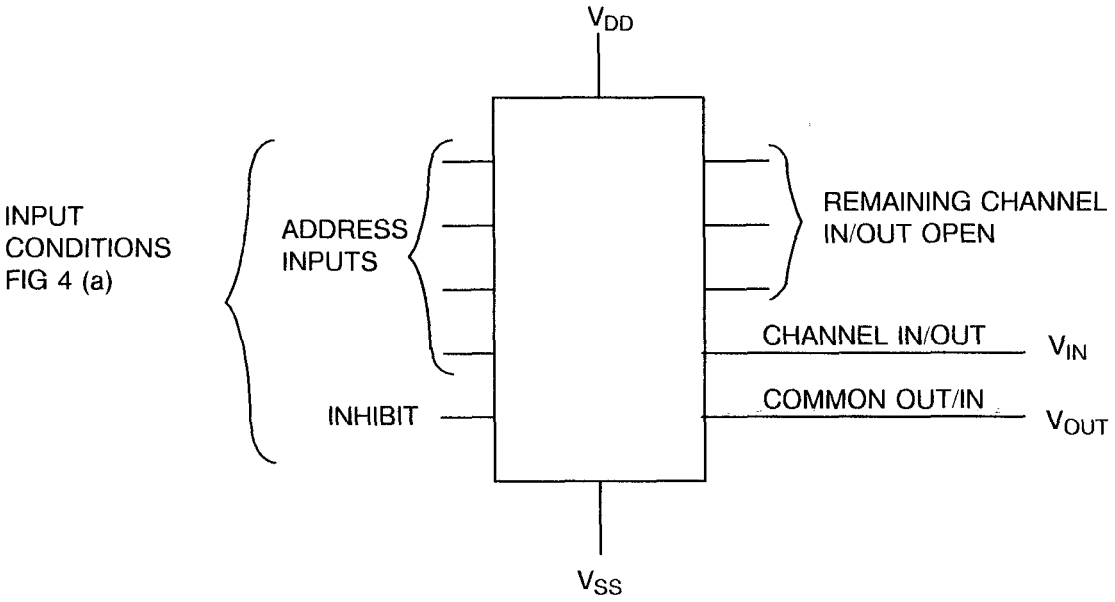
VOLTAGE WAVEFORMS



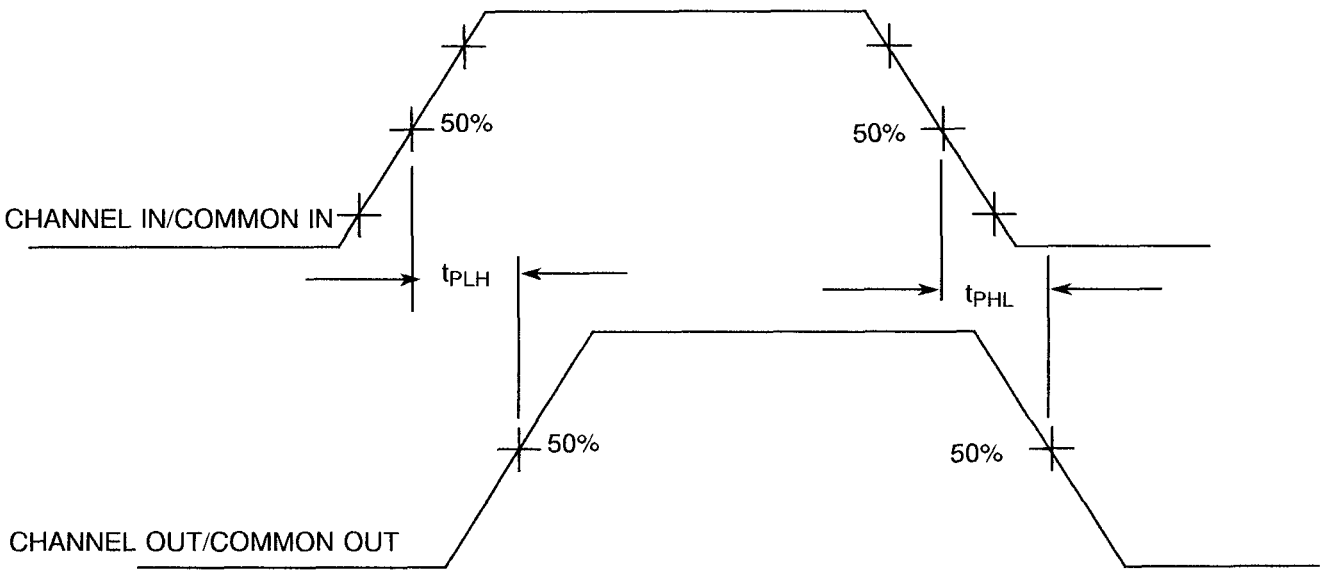
NOTES 1. Pulse Generator - $V_P = V_{DD}$, t_r and $t_f \leq 15$ns, f = 500kHz.

FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS (CONTINUED)

FIGURE 4 (g) - PROPAGATION DELAY, CHANNEL OR COMMON IN TO COMMON OR CHANNEL OUT



VOLTAGE WAVEFORMS



NOTES 1. Pulse Generator - $V_P = 0$ to V_{DD}, t_r and $t_f \leq 15$ns, f = 500kHz.

TABLE 4 - PARAMETER DRIFT VALUES

NO.	CHARACTERISTICS	SYMBOL	SPEC. AND/OR TEST METHOD	TEST CONDITIONS	CHANGE LIMITS (Δ)	UNIT
3 to 18	Quiescent Current	I_{DD}	As per Table 2	As per Table 2	± 75	nA
Note (1)	Channel on Resistance	R_{ON1}	As per Table 2	As per Table 2	± 50	Ω
Note (2)	Channel on Resistance	R_{ON2}	As per Table 2	As per Table 2	± 15	Ω
545	Threshold Voltage N-Channel	V_{THN}	As per Table 2	As per Table 2	± 0.3	V
546	Threshold Voltage P-Channel	V_{THP}	As per Table 2	As per Table 2	± 0.3	V

NOTES

1. Test Numbers: 63, 68, 73, 78, 83, 88, 93, 175, 180, 185, 190, 195, 200, 205.

2. Test Numbers: 278, 292, 297, 302, 307, 312, 317, 322, 415, 420, 425, 430, 435, 440, 445, 450.

TABLE 5(a) - CONDITIONS FOR BURN-IN HIGH TEMPERATURE REVERSE BIAS, N-CHANNELS

NO.	CHARACTERISTICS	SYMBOL	CONDITION	UNIT
1	Ambient Temperature	T_{amb}	+125 (+0 -5)	°C
2	Outputs - (Pins D/F 2-3-4-5-6-7-8-9-16-17-18-19-20-21-22-23) (Pins C 2-3-5-6-7-8-9-10-19-20-21-22-23-24-26-27)	V_{CH}	V_{DD}	Vdc
3	Common Out/In (Pin D/F 1) (Pin C 1)	V_{COM}	Ground	Vdc
4	Inputs - (Pins D/F 10-11-13-14-15) (Pins C 12-13-15-16-17)	V_{IN}	V_{DD}	Vdc
5	Positive Supply Voltage (Pin D/F 24) (Pin C 28)	V_{DD}	15	Vdc
6	Negative Supply Voltage (Pin D/F 12) (Pin C 14)	V_{SS}	Ground	Vdc

NOTES

1. Common OUT/IN Protection Resistor = 2kΩ minimum to 47kΩ maximum.

TABLE 5(b) - CONDITIONS FOR BURN-IN HIGH TEMPERATURE REVERSE BIAS, P-CHANNELS

NO.	CHARACTERISTICS	SYMBOL	CONDITION	UNIT
1	Ambient Temperature	T_{amb}	+125 (+0 -5)	°C
2	Outputs - (Pins D/F 2-3-4-5-6-7-8-9-16-17-18-19-20-21-22-23) (Pins C 2-3-5-6-7-8-9-10-19-20-21-22-23-24-26-27)	V_{CH}	Ground	Vdc
3	Common In/Out (Pin D/F 1) (Pin C 1)	V_{COM}	Ground	Vdc
4	Inputs - (Pins D/F 10-11-13-14-15) (Pins C 12-13-15-16-17)	V_{IN}	V_{SS}	Vdc
5	Positive Supply Voltage (Pin D/F 24) (Pin C 28)	V_{DD}	15	Vdc
6	Negative Supply Voltage (Pin D/F 12) (Pin C 14)	V_{SS}	Ground	Vdc

NOTES

1. Common OUT/IN Protection Resistor = 2kΩ minimum to 47kΩ maximum.

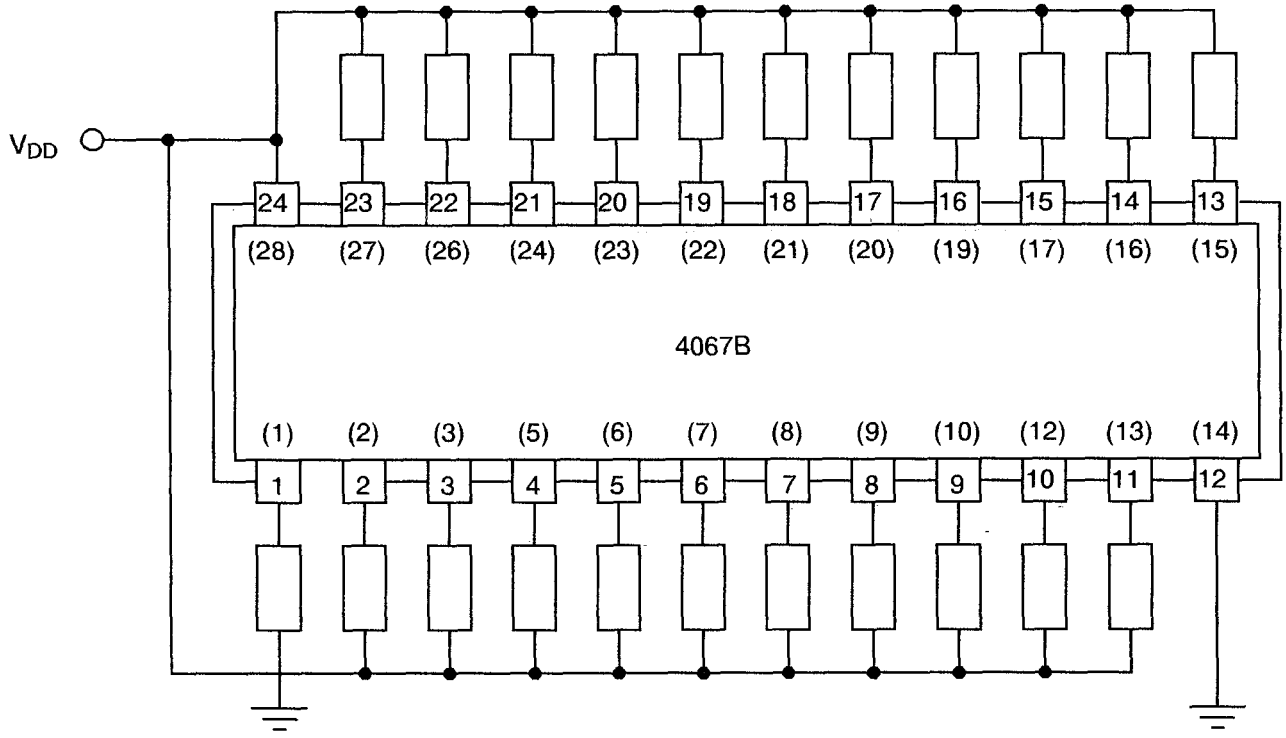
TABLE 5(c) - CONDITIONS FOR BURN-IN DYNAMIC

NO.	CHARACTERISTICS	SYMBOL	CONDITION	UNIT
1	Ambient Temperature	T_{amb}	+125 +0 -5	°C
2	Outputs - (Pins D/F 2-3-4-5-6-7-8-9-16-17-18-19-20-21-22-23) (Pins C 2-3-5-6-7-8-9-10-19-20-21-22-23-24-26-27)	V_{CH}	V_{DD}	Vdc
3	Common OUT/IN (Pin D/F 1) (Pin C 1)	V_{COM}	Ground	Vdc
4	Inputs - (Pins D/F 10-11-13-14-15) (Pins C 12-13-15-16-17)	V_{IN}	V_{GEN}	Vdc
7	Pulse Voltage (Binary Counter)	V_{GEN}	0 to V_{DD}	Vac
8	Pulse Frequency Binary Counter Square Wave	f	500k	Hz
10	Positive Supply Voltage (Pin D/F 24) (Pin C 28)	V_{DD}	15	Vdc
11	Negative Supply Voltage (Pin D/F 12) (Pin C 14)	V_{SS}	Ground	Vdc

NOTES

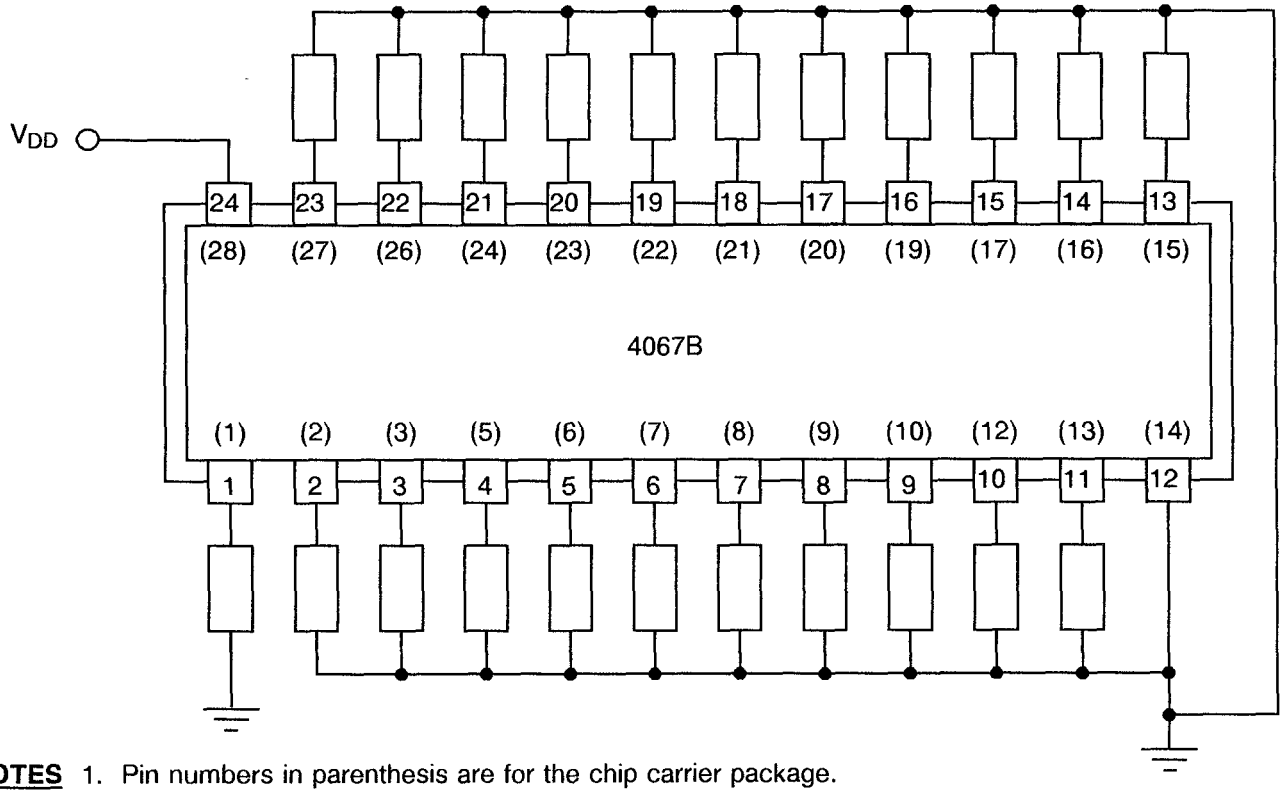
1. Common OUT/IN Protection Resistor = 2kΩ minimum to 47kΩ maximum.

FIGURE 5 (a) - ELECTRICAL CIRCUIT FOR BURN-IN HIGH TEMPERATURE REVERSE BIAS, N-CHANNELS



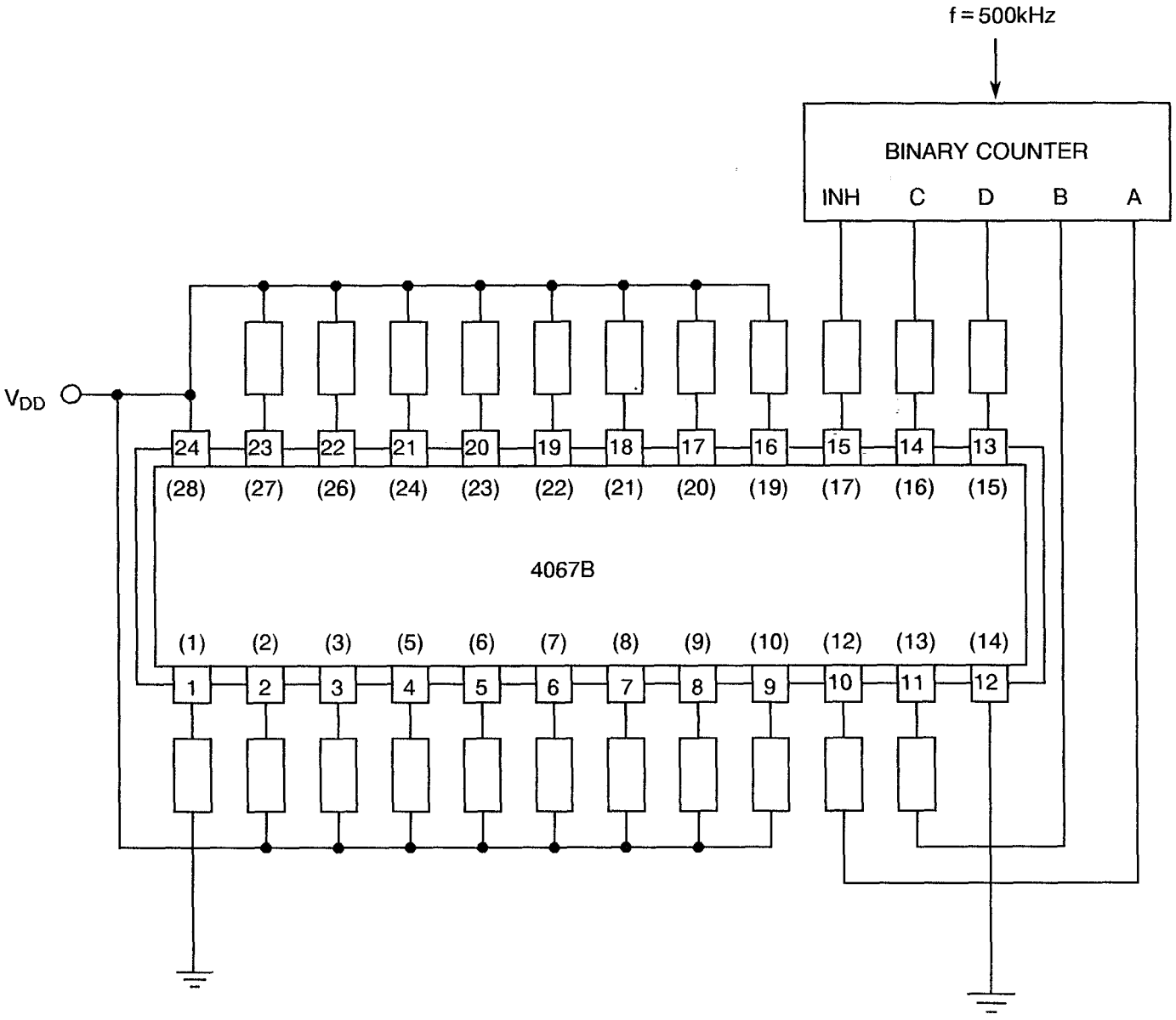
NOTES 1. Pin numbers in parenthesis are for the chip carrier package.

FIGURE 5(b) - ELECTRICAL CIRCUIT FOR BURN-IN HIGH TEMPERATURE REVERSE BIAS, P-CHANNELS



NOTES 1. Pin numbers in parenthesis are for the chip carrier package.

FIGURE 5 (c) - ELECTRICAL CIRCUIT FOR BURN-IN DYNAMIC



NOTES 1. Pin numbers in parenthesis are for the chip carrier package.

4.8 ENVIRONMENTAL AND ENDURANCE TESTS

4.8.1 Electrical Measurements on Completion of Environmental Tests

The parameters to be measured on completion of environmental tests are scheduled in Table 6. Unless otherwise stated, the measurements shall be performed at $T_{amb} = +22 \pm 3$ °C.

4.8.2 Electrical Measurements at Intermediate Points during Endurance Tests

The parameters to be measured at intermediate points during endurance tests are as scheduled in Table 6 of this specification.

4.8.3 Electrical Measurements on Completion of Endurance Tests

The parameters to be measured on completion of endurance testing are as scheduled in Table 6 of this specification. Unless otherwise stated, the measurements shall be performed at $T_{amb} = +22 \pm 3$ °C.

4.8.4 Conditions for Operating Life Test

The requirements for operating life testing are specified in Section 9 of ESA/SCC Generic Specification No. 9000. The conditions for operating life testing shall be as specified in Table 5(c) of this specification.

4.8.5 Electrical Circuits for Operating Life Tests

Circuits for use in performing the operating life test are shown in Figure 5(c) of this specification.

4.8.6 Conditions for High Temperature Storage Test

The requirements for the high temperature storage test are specified in ESA/SCC Generic Specification No. 9000. The temperature to be applied shall be the maximum storage temperature specified in Table 1(b) of this specification.

TABLE 6 - ELECTRICAL MEASUREMENTS ON COMPLETION OF ENVIRONMENTAL TESTS AND AT INTERMEDIATE POINTS AND ON COMPLETION OF ENDURANCE TESTING

NO.	CHARACTERISTICS	SYMBOL	SPEC. AND/OR TEST METHOD	TEST CONDITIONS	CHANGE LIMITS (Δ)			UNIT
						MIN	MAX	
1	Functional Test	-	As per Table 2	As per Table 2	-	-	-	-
3 to 18	Quiescent Current	I_{DD}	As per Table 2	As per Table 2	± 75	-	-	nA
19 to 23	Input Current Low Level Address or Inhibit	I_{IL}	As per Table 2	As per Table 2	-	-	-50	nA
24 to 28	Input Current High Level Address or Inhibit	I_{IH}	As per Table 2	As per Table 2	-	-	50	nA
29 to 44	Channel Off Leakage Current (Any Channel)	I_{OFF1}	As per Table 2	As per Table 2	-	-	-100	nA
45 to 60	Channel Off Leakage Current (Any Channel)	I_{OFF2}	As per Table 2	As per Table 2	-	-	100	nA
61	Channel Off Leakage Current (All Channels)	I_{OFF3}	As per Table 2	As per Table 2	-	-	100	nA
62	Channel Off Leakage Current (All Channels)	I_{OFF4}	As per Table 2	As per Table 2	-	-	-100	nA
63 to 286	Channel On Resistance	R_{ON1}	As per Table 2	As per Table 2	± 50	-	-	Ω
287 to 542	Channel On Resistance	R_{ON2}	As per Table 2	As per Table 2	± 15	-	-	Ω
543	Input Voltage Low Level (Noise Immunity) (Functional Test)	V_{IL1}	As per Table 2	As per Table 2	-	-	0.5	V
	Input Voltage High Level (Noise Immunity) (Functional Test)	V_{IH1}			-	4.5	-	
545	Threshold Voltage N-Channel	V_{THN}	As per Table 2	As per Table 2	± 0.3	-	-	V
546	Threshold Voltage P-Channel	V_{THP}	As per Table 2	As per Table 2	± 0.3	-	-	V

APPENDIX 'A'

AGREED DEVIATIONS FOR STMICROELECTRONICS (F)

ITEMS AFFECTED	DESCRIPTION OF DEVIATION
Para. 4.2.3	Para. 9.23, High Temperature Reverse Bias Burn-in: The temperature limits of MIL-STD-883, Para. 4.5.8(c) may be used. Para. 9.24, Power Burn-in: The temperature limits of MIL-STD-883, Para. 4.5.8(c) may be used.
Para. 4.2.4	Para. 9.21.1, Operating Life during Qualification Testing: The temperature limits of MIL-STD-883, Para. 4.5.8(c) may be used.
Para. 4.2.5	Para. 9.21.2, Operating Life during Lot Acceptance Testing: The temperature limits of MIL-STD-883, Para. 4.5.8(c) may be used.